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(54) **LITHOGRAPHIC APPARATUS, REMOVABLE MEMBER AND DEVICE MANUFACTURING METHOD**

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C09J 7/02 (2006.01)
C09J 7/04 (2006.01)

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B32B 2307/73 (2013.01); *B32B 2307/546* (2013.01); *B32B 2405/00* (2013.01)

USPC **355/30**; 428/343; 428/353; 428/354; 428/355 R

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USPC **355/30**; 156/313; 277/637; 428/343–355 N

See application file for complete search history.

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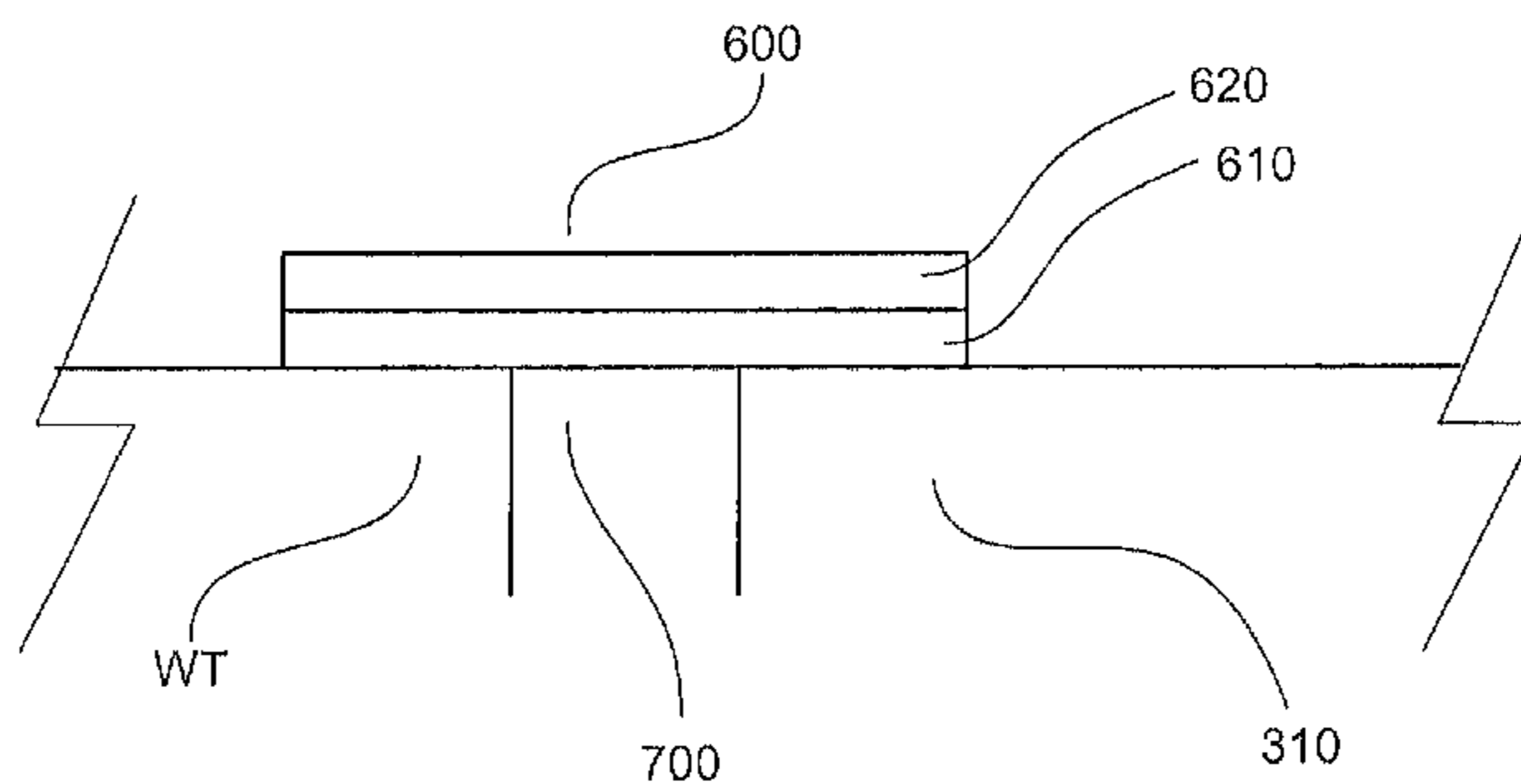
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(57) **ABSTRACT**

A sealing member is provided to prevent immersion liquid ingress to a gap between components. The sealing member has a plastic or polymer sealing portion that is adhered to the components forming the gap being sealed. The sealing member is constructed so as to reduce the force-coupling, in particular the time-related force-coupling, between the components being sealed.

20 Claims, 15 Drawing Sheets



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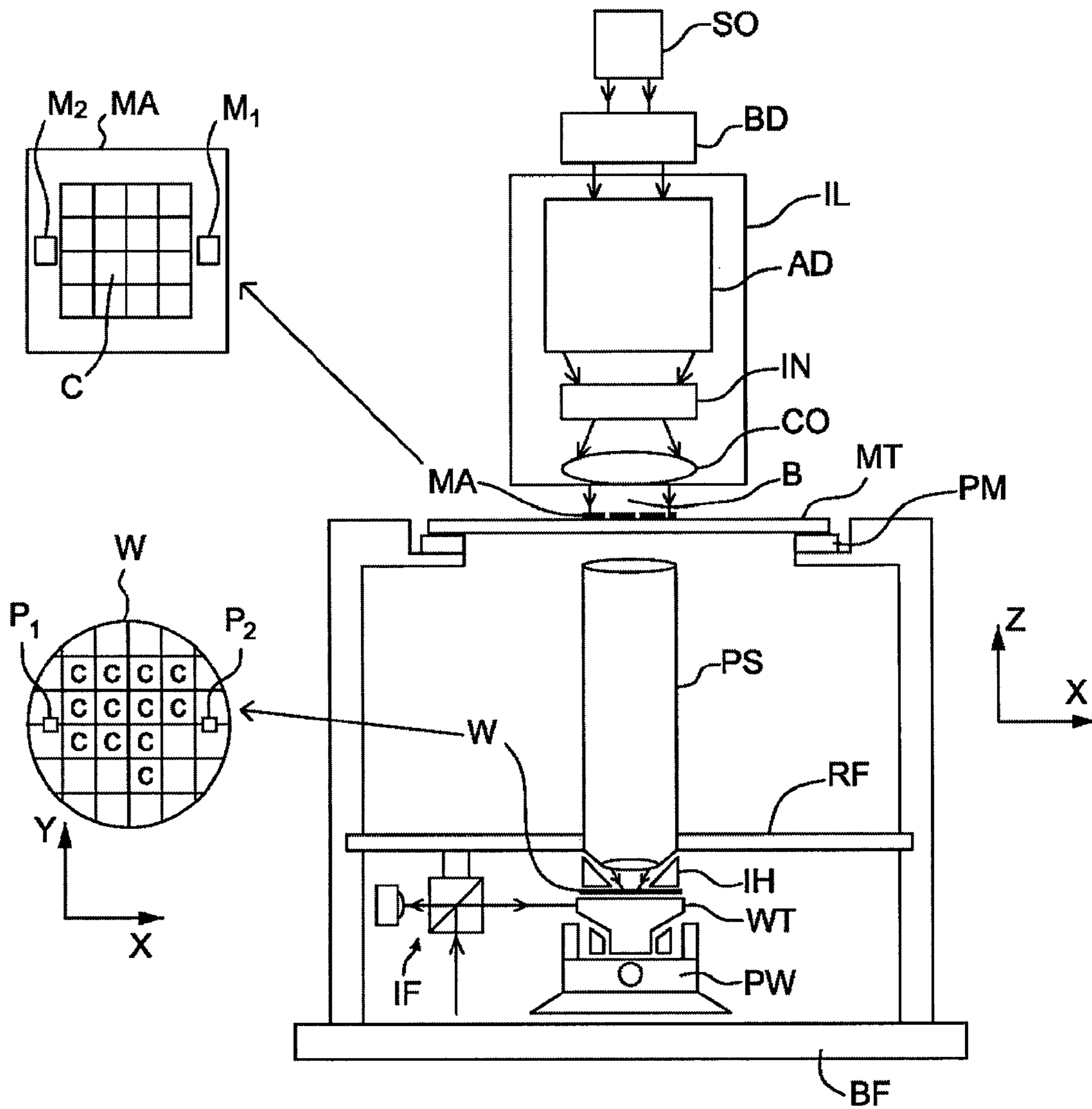
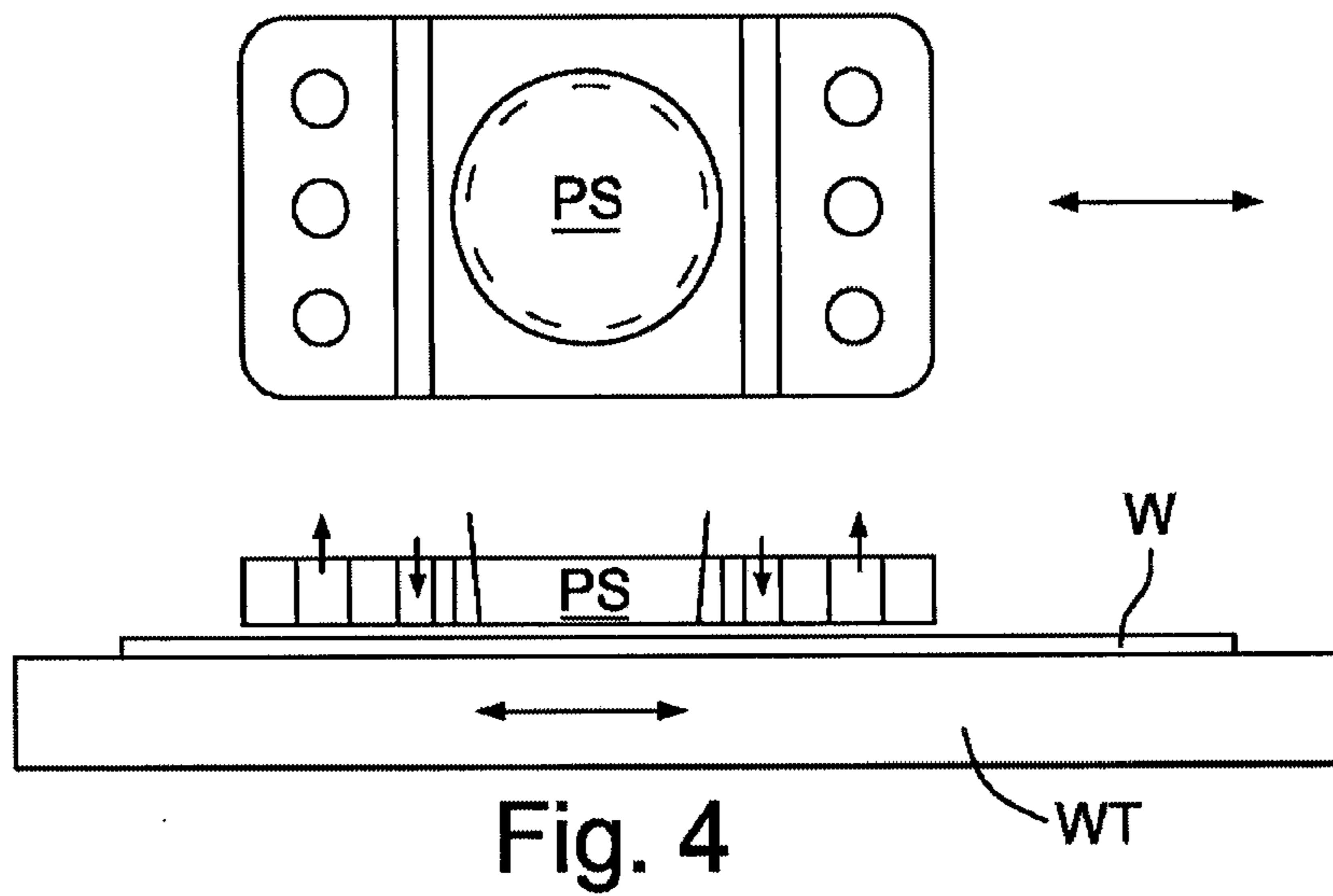
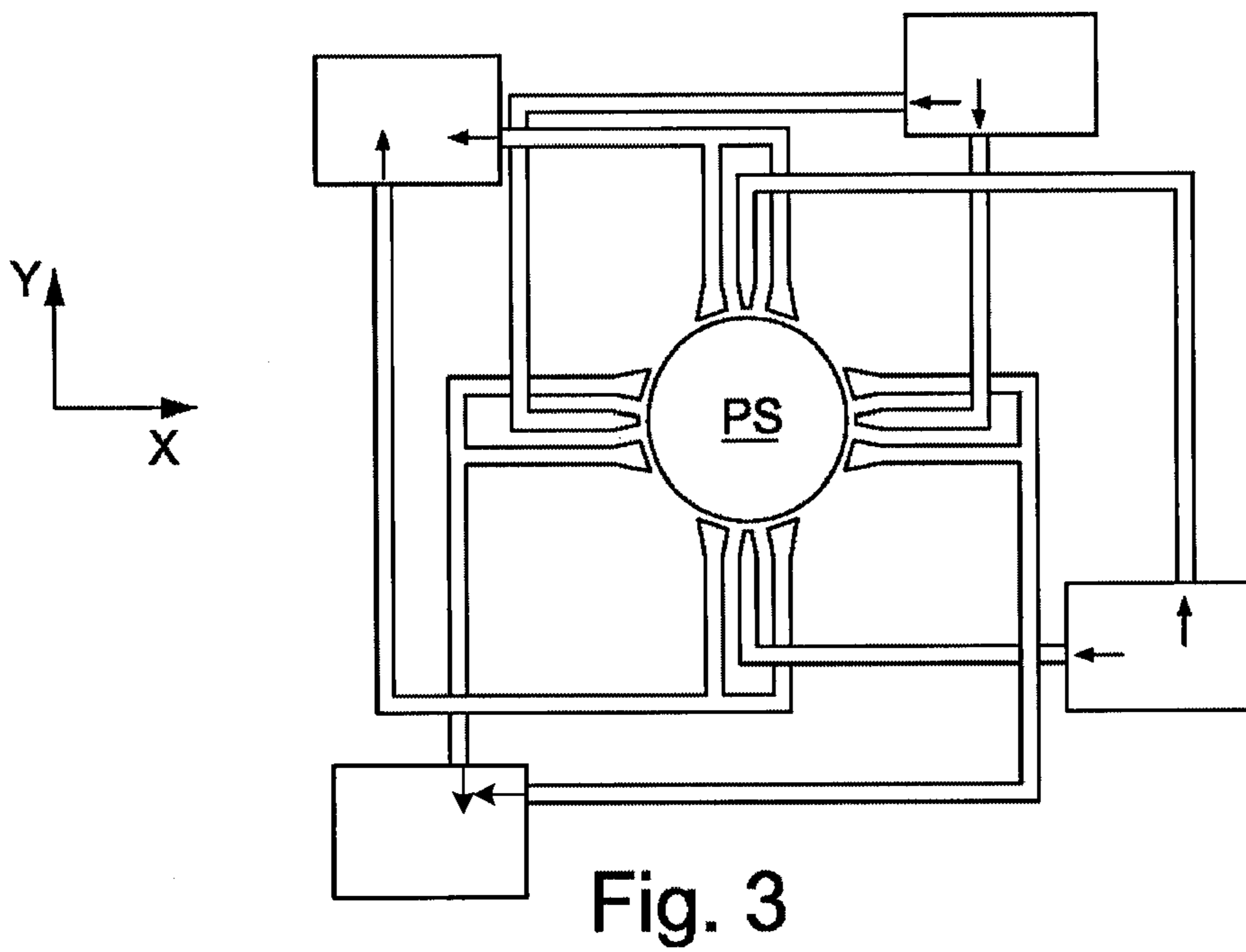
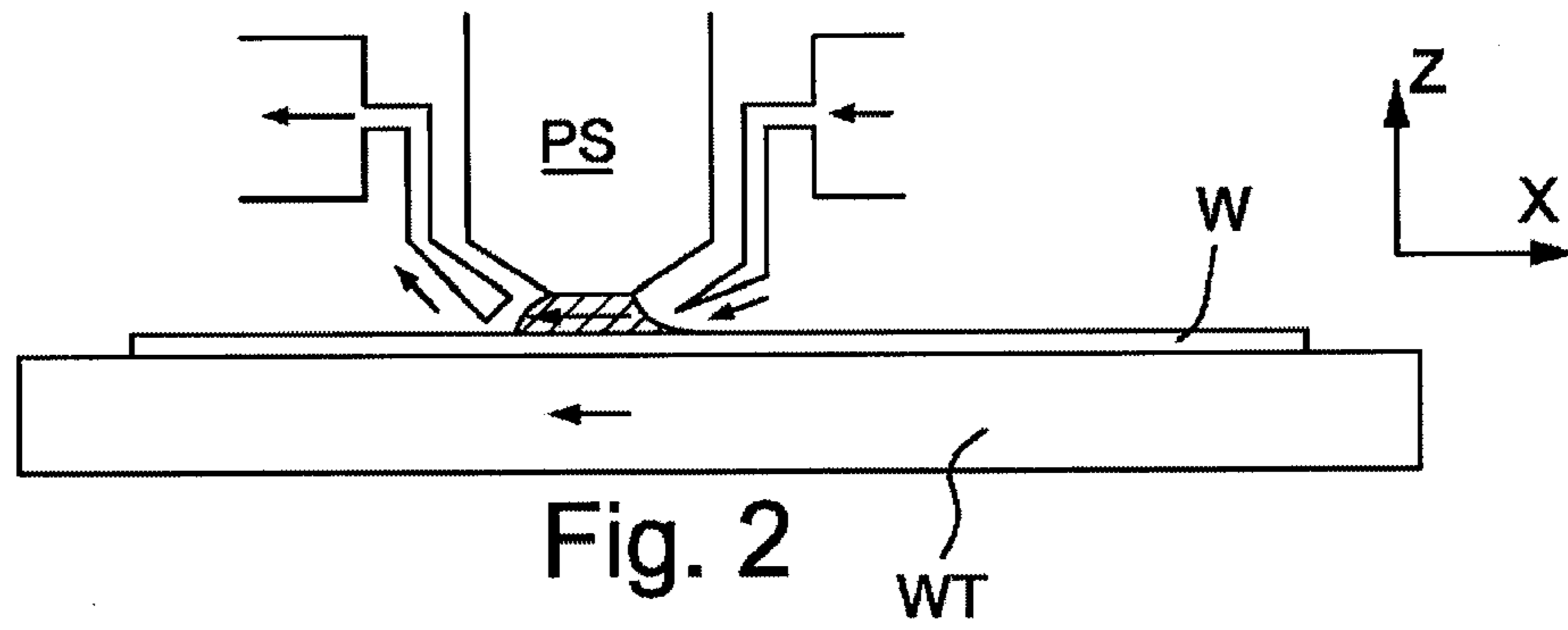
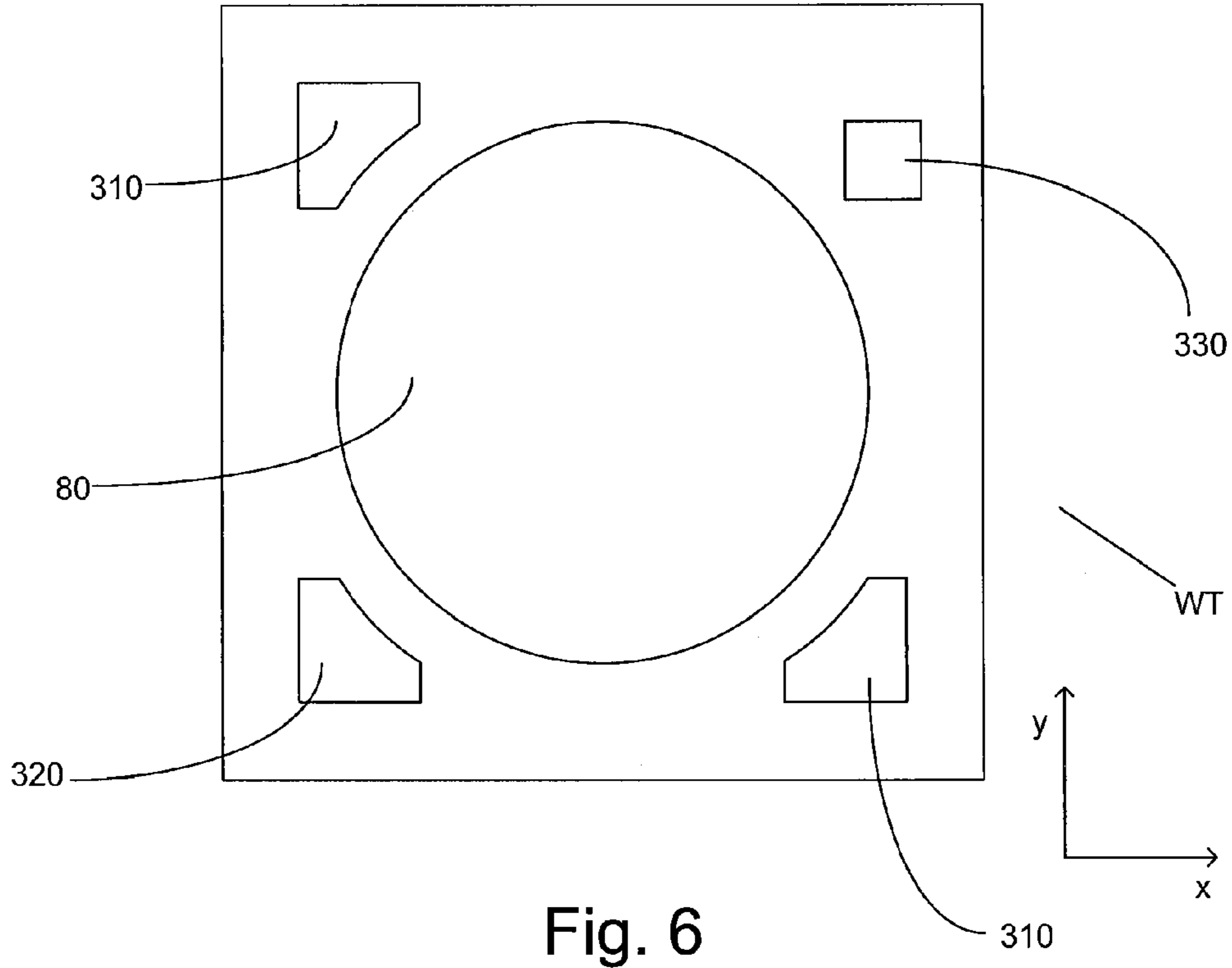
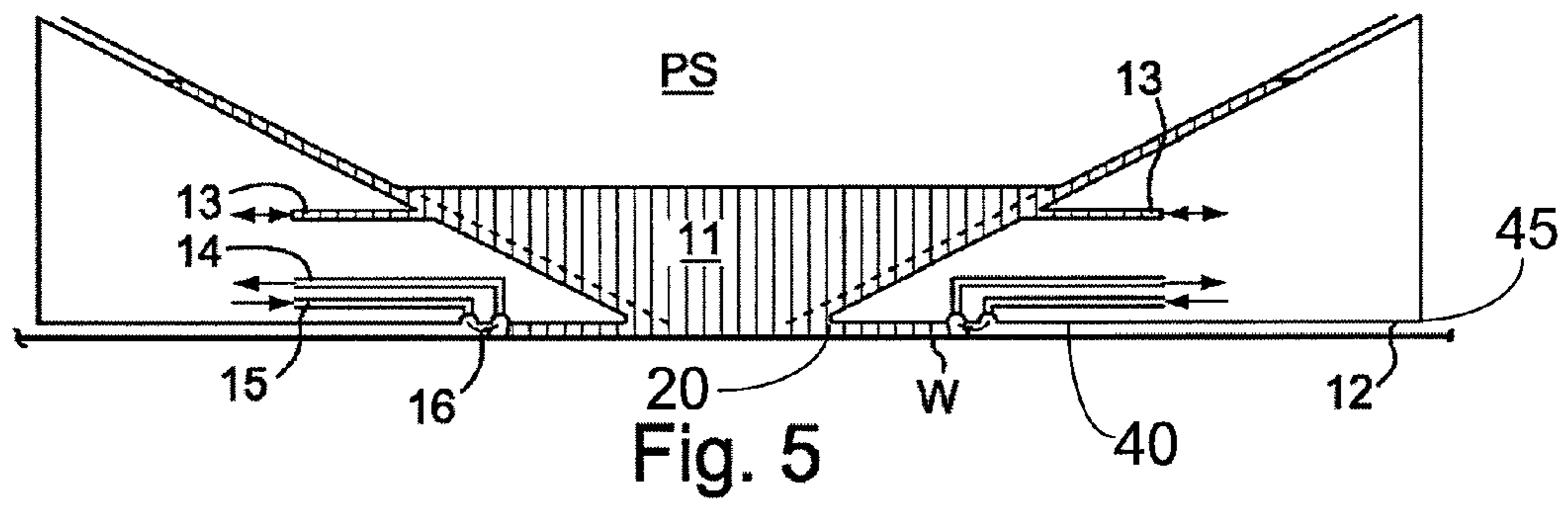


Fig. 1





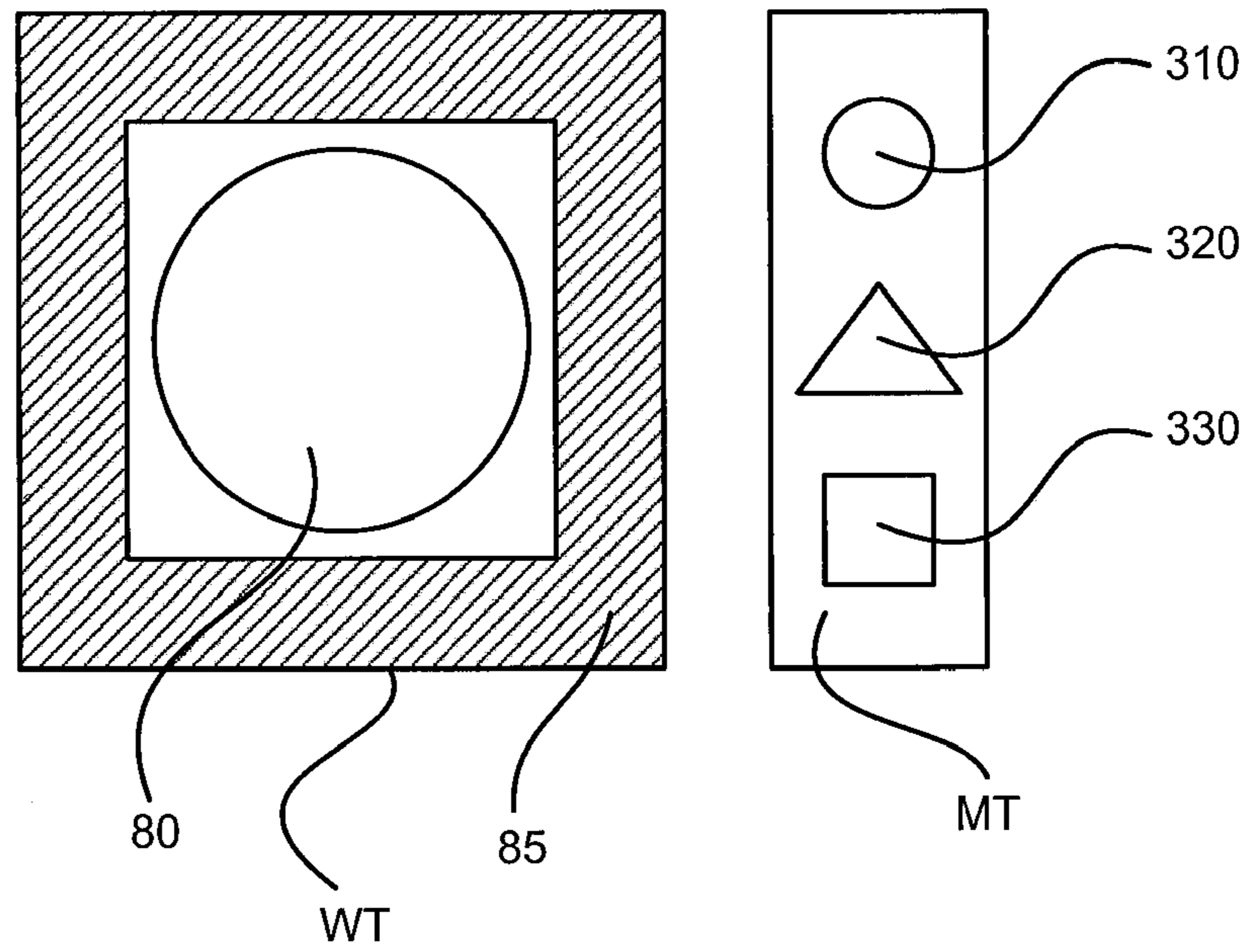


Fig. 7

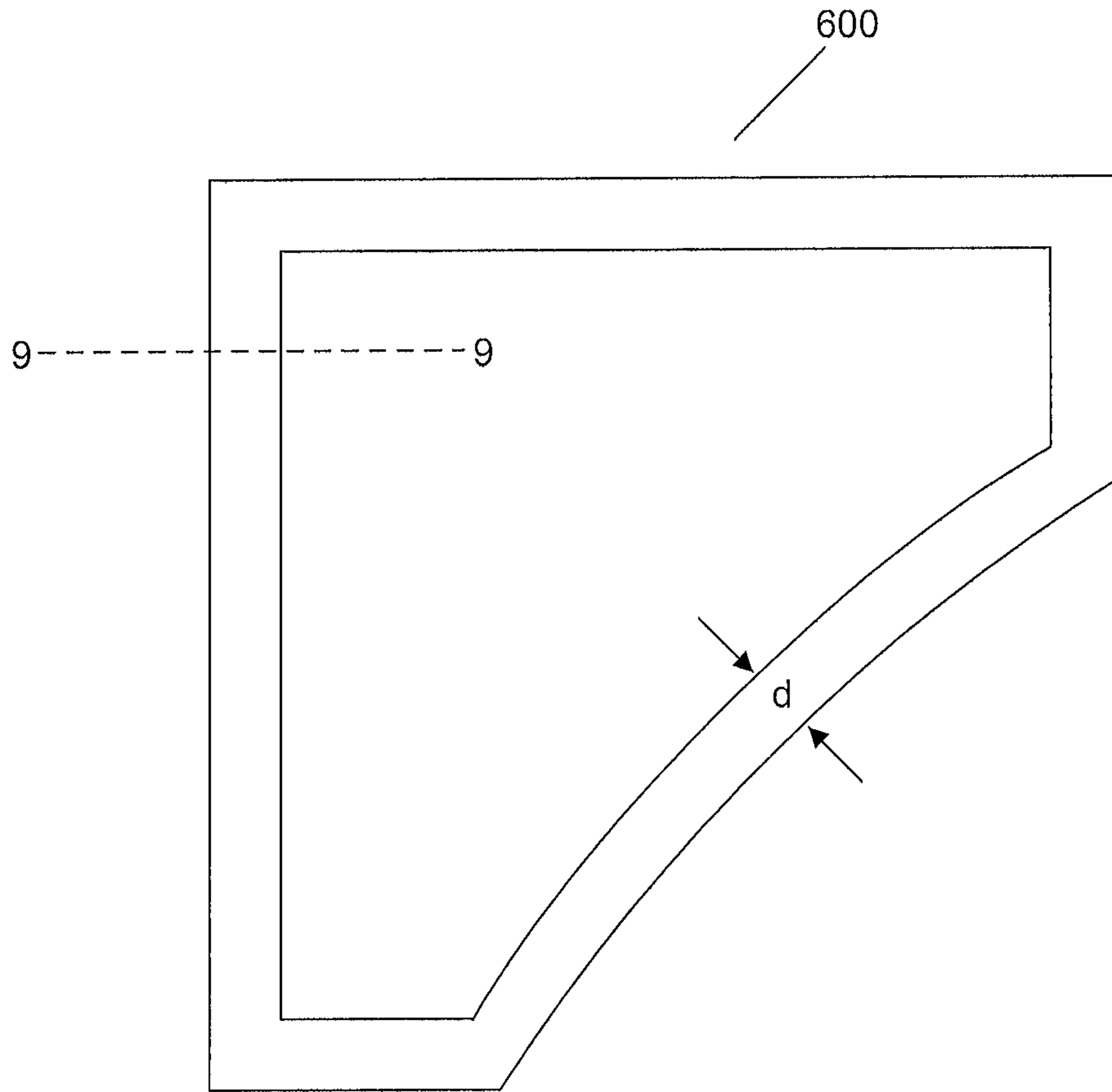
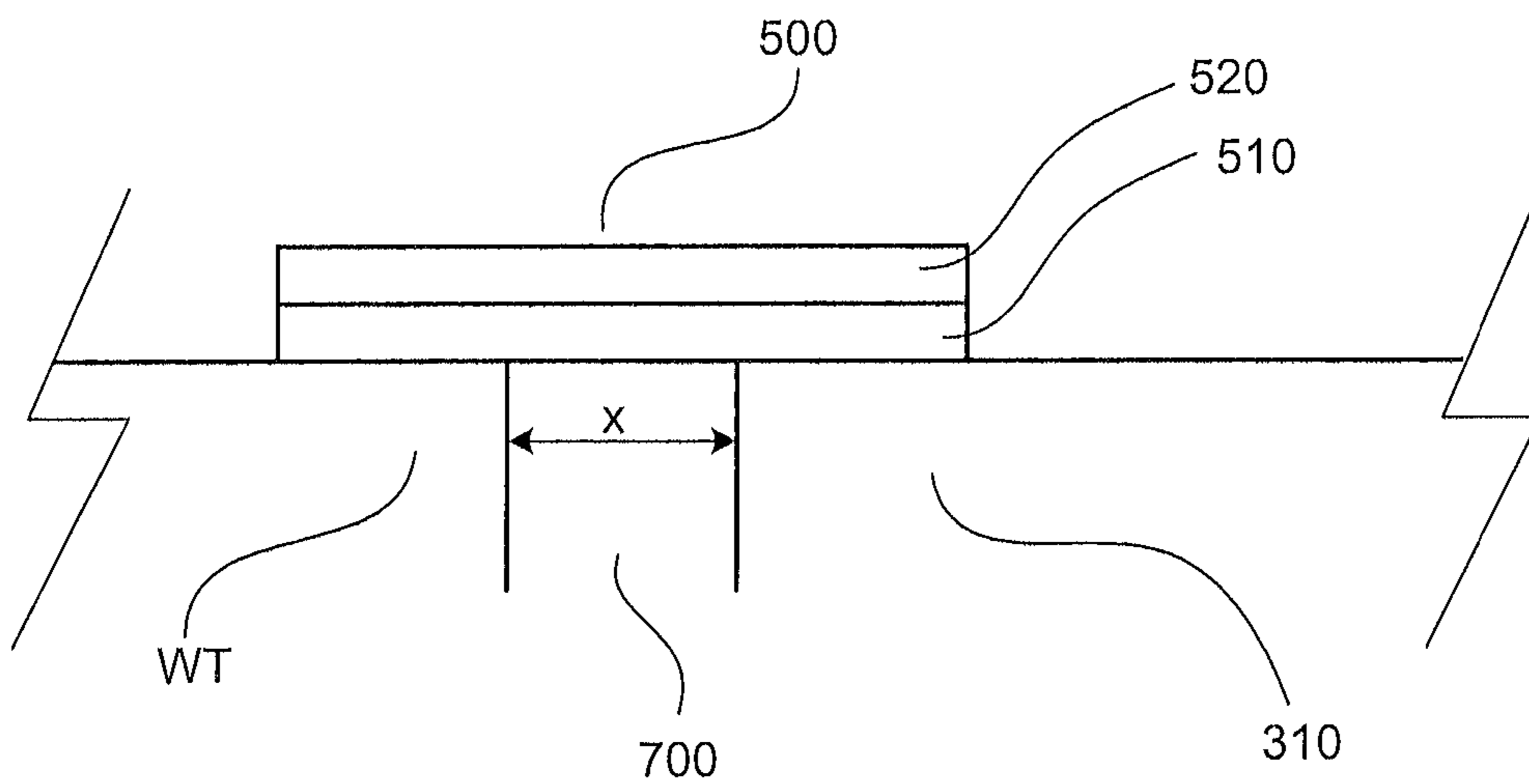
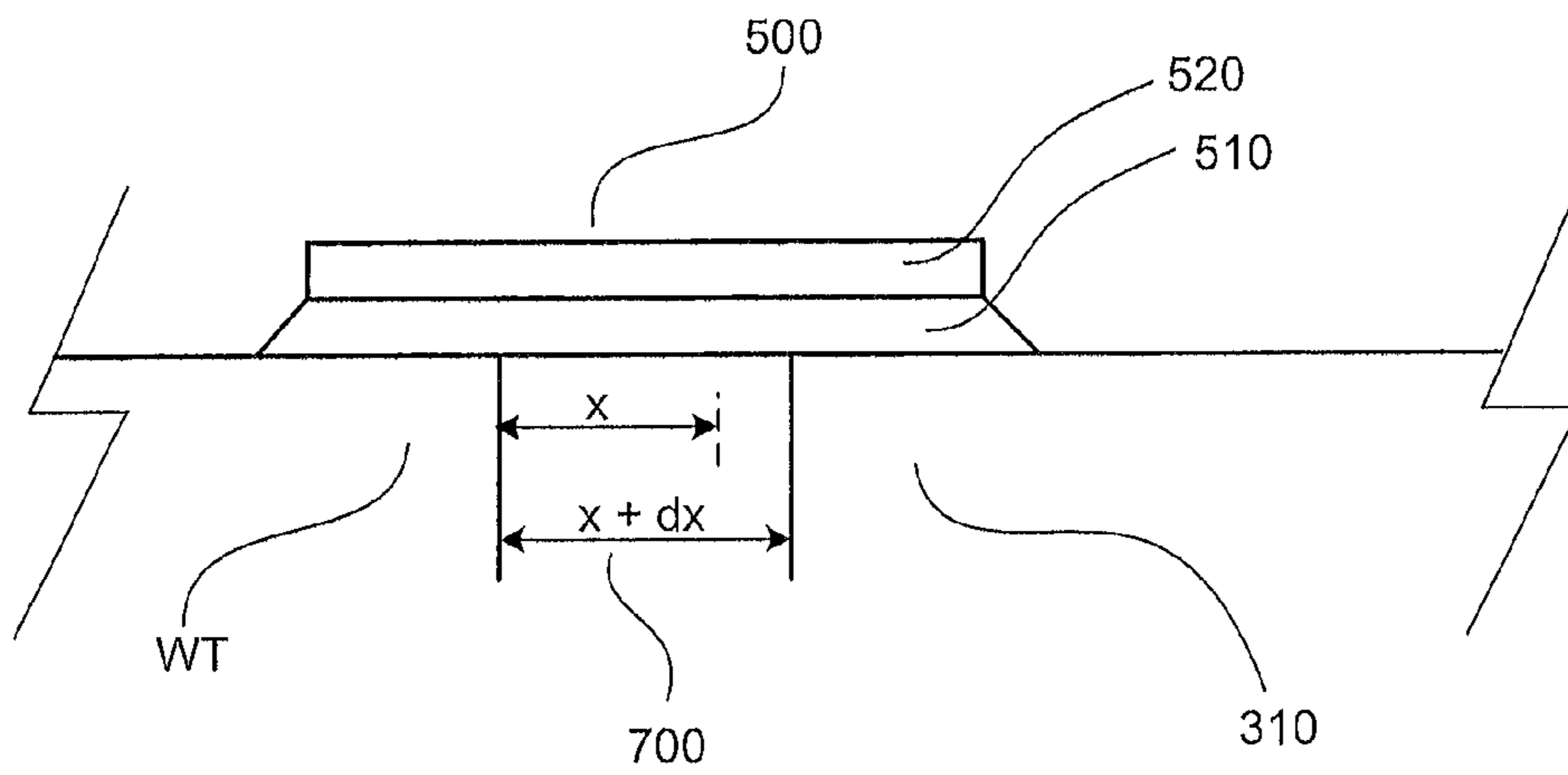


Fig. 8



-- PRIOR ART --

Fig. 9



-- PRIOR ART --

Fig. 10

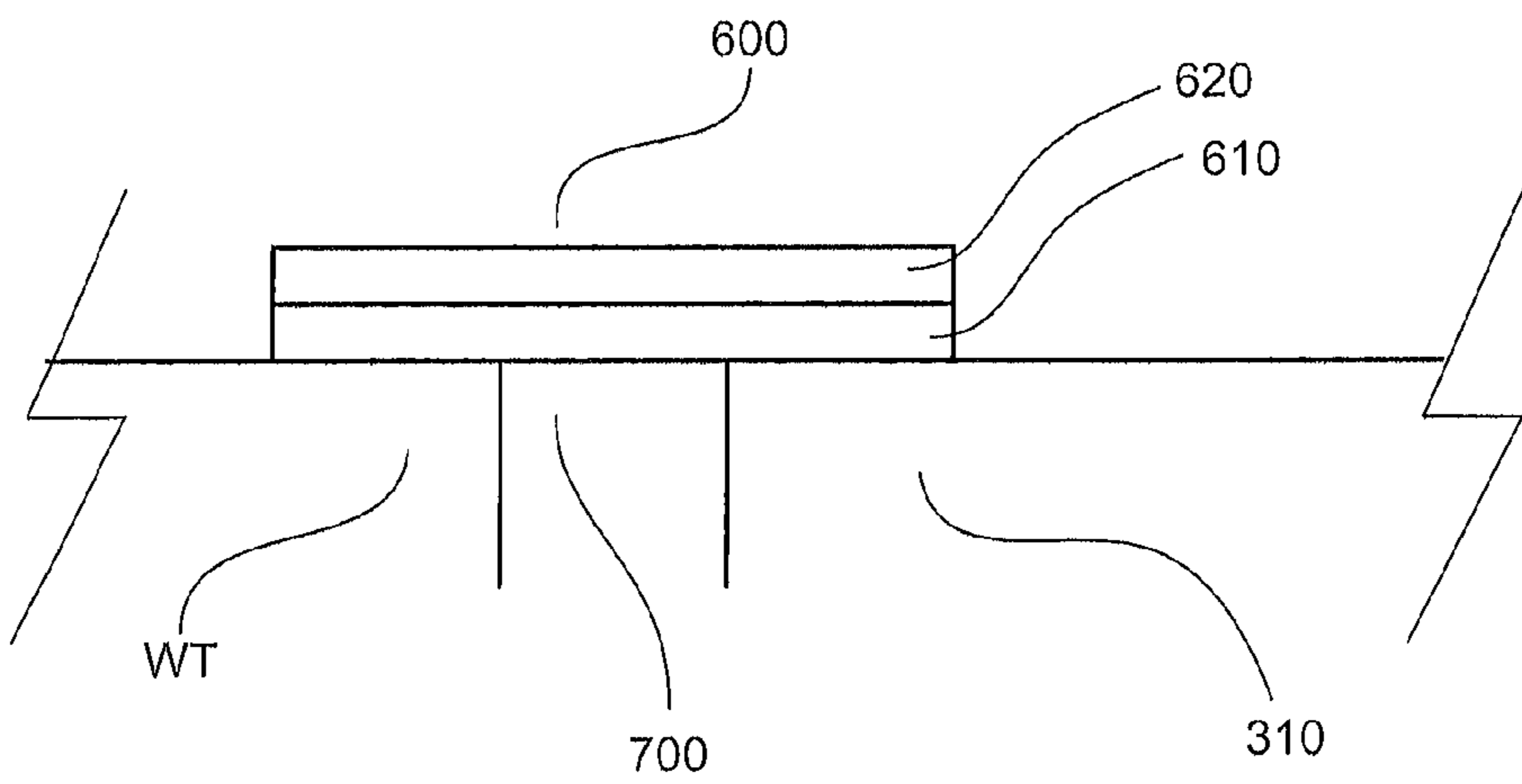


Fig. 11

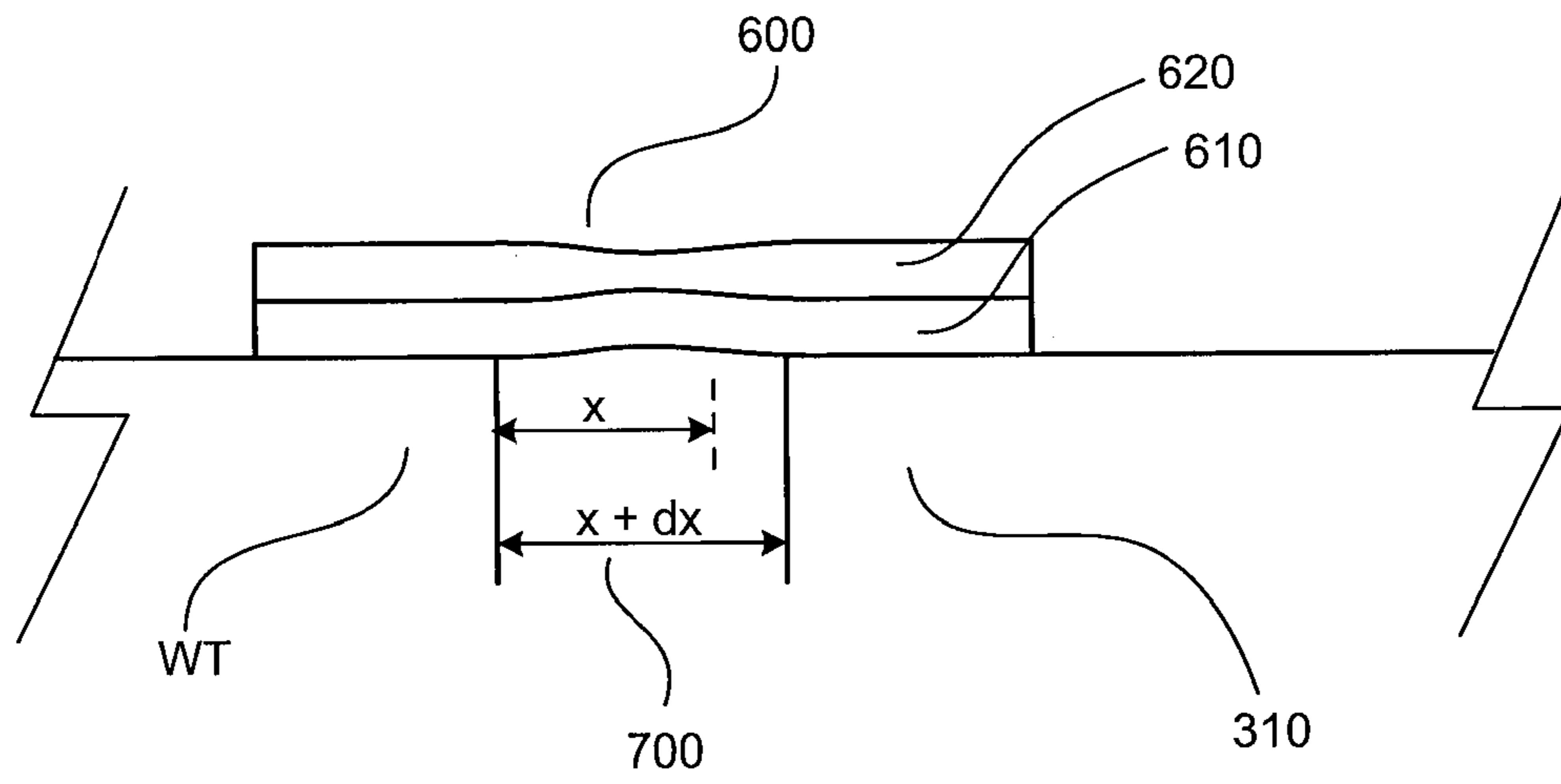


Fig. 12

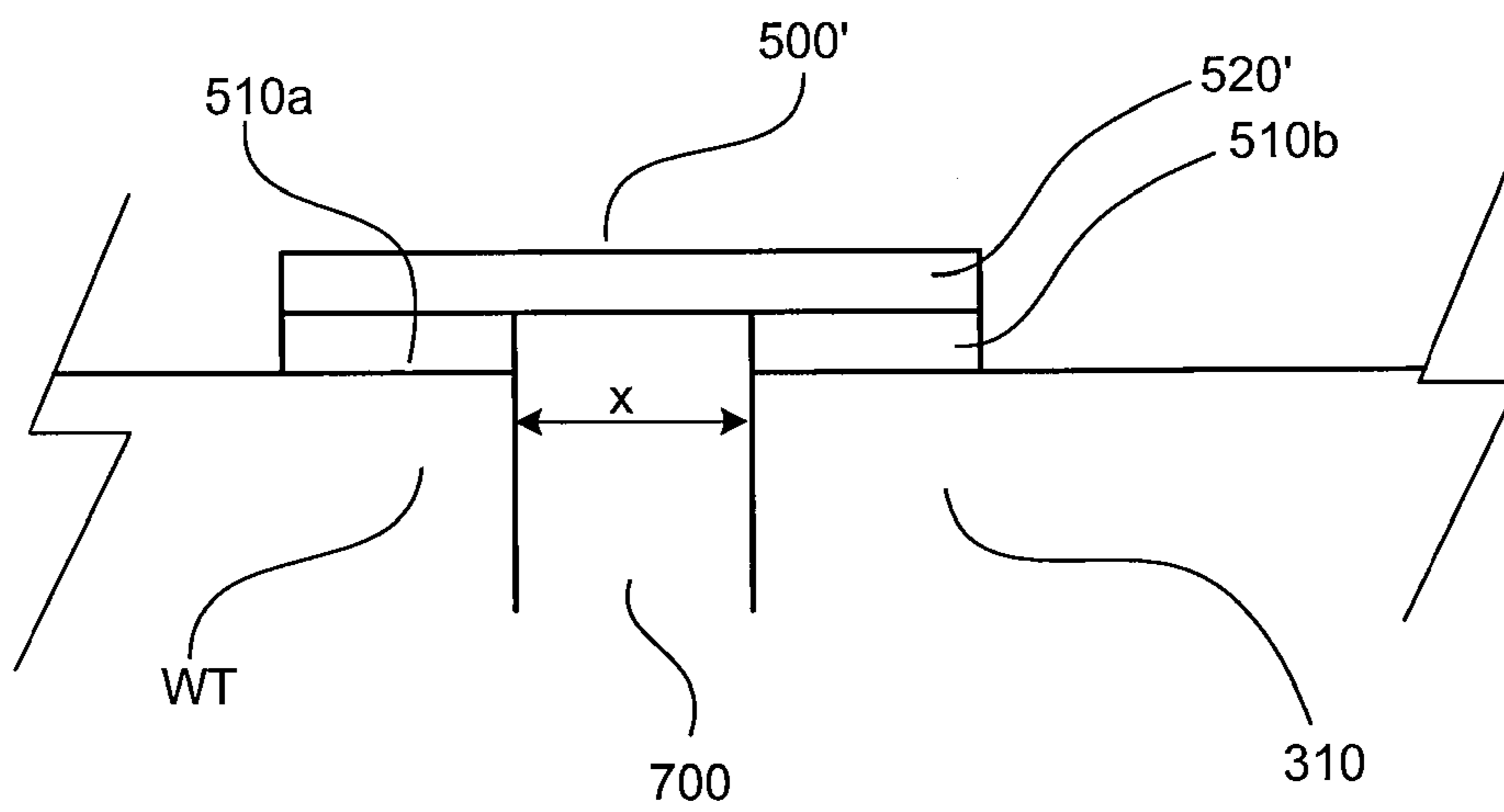


Fig. 13

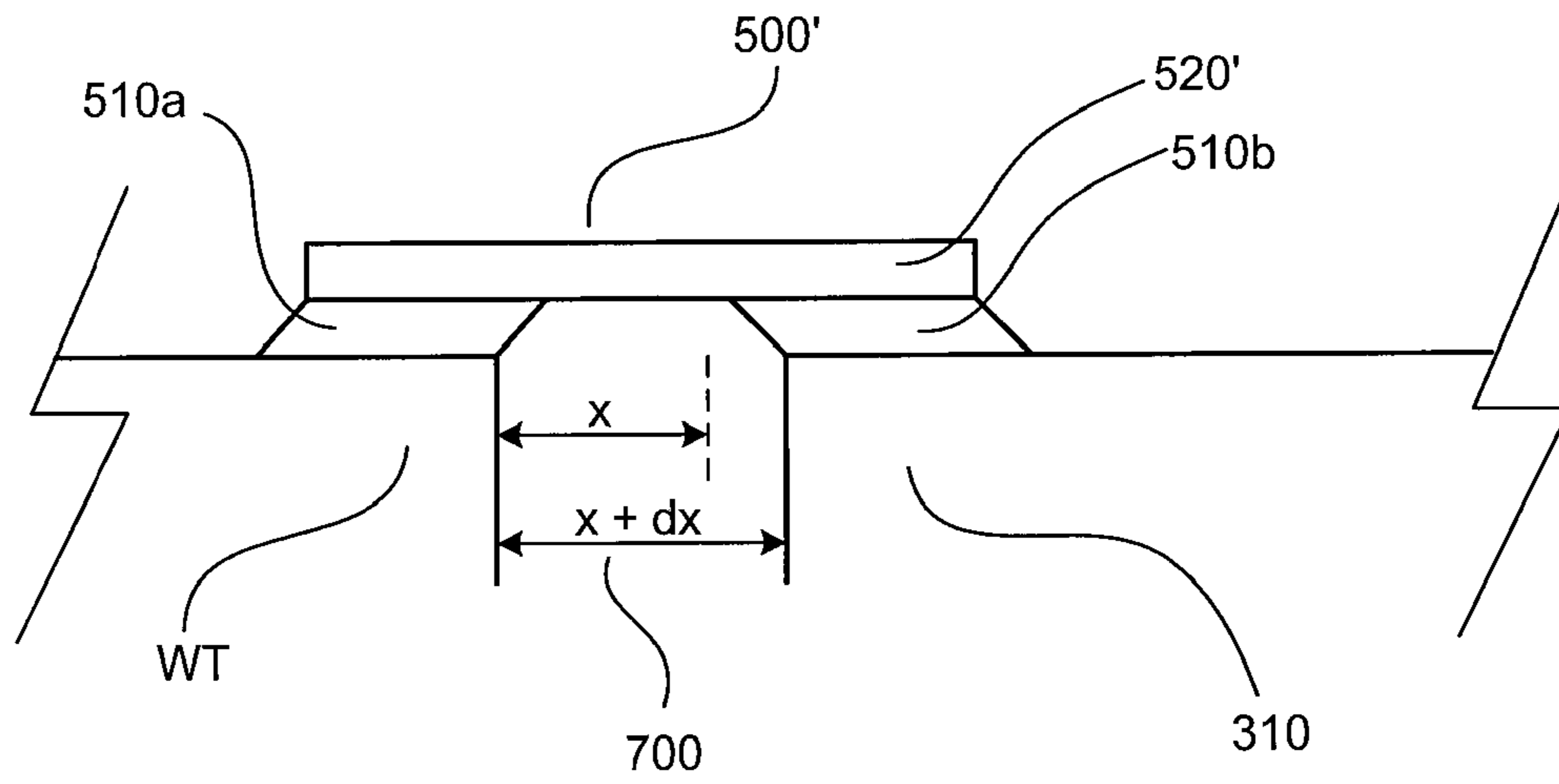


Fig. 14

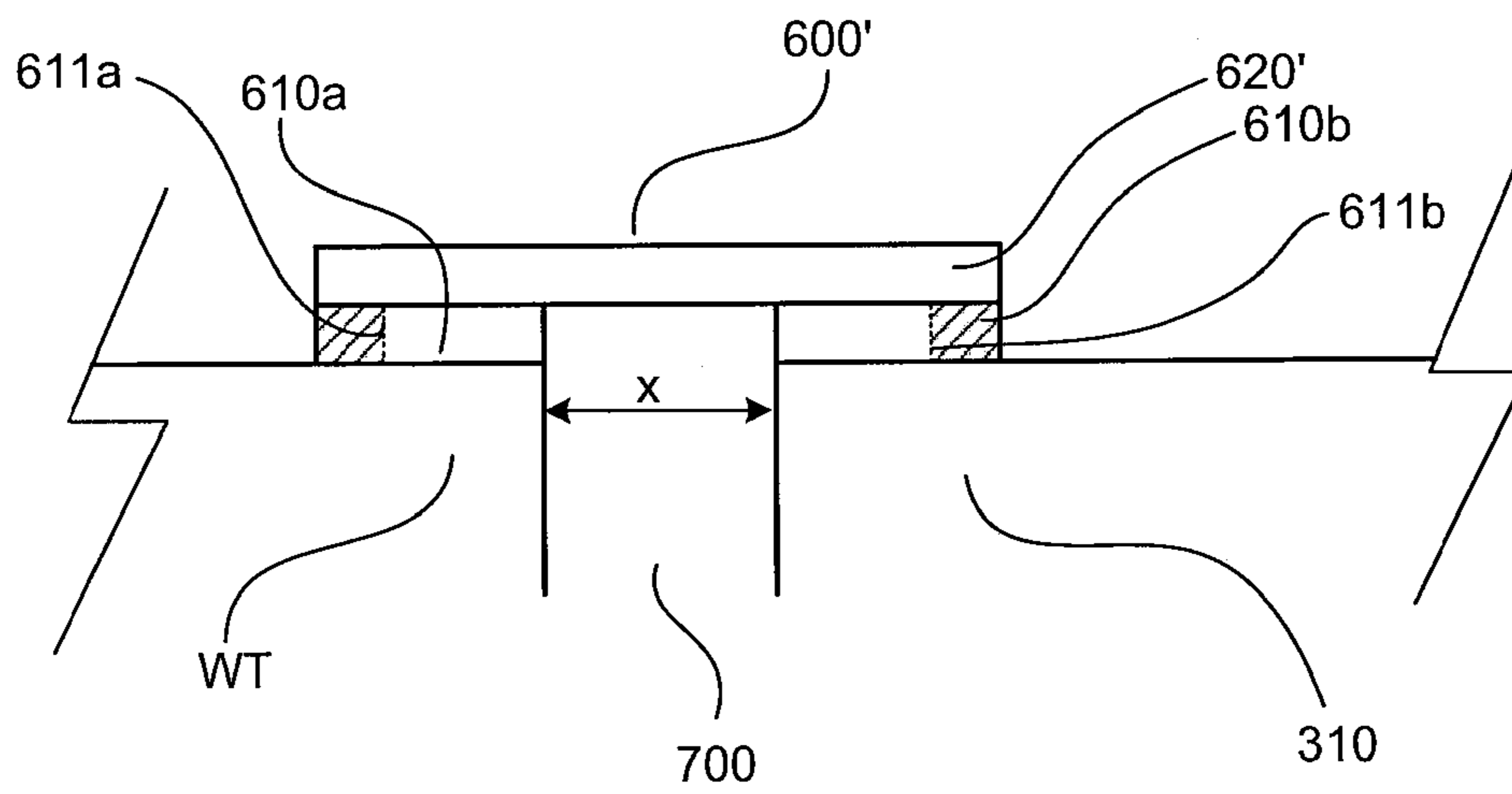


Fig. 15

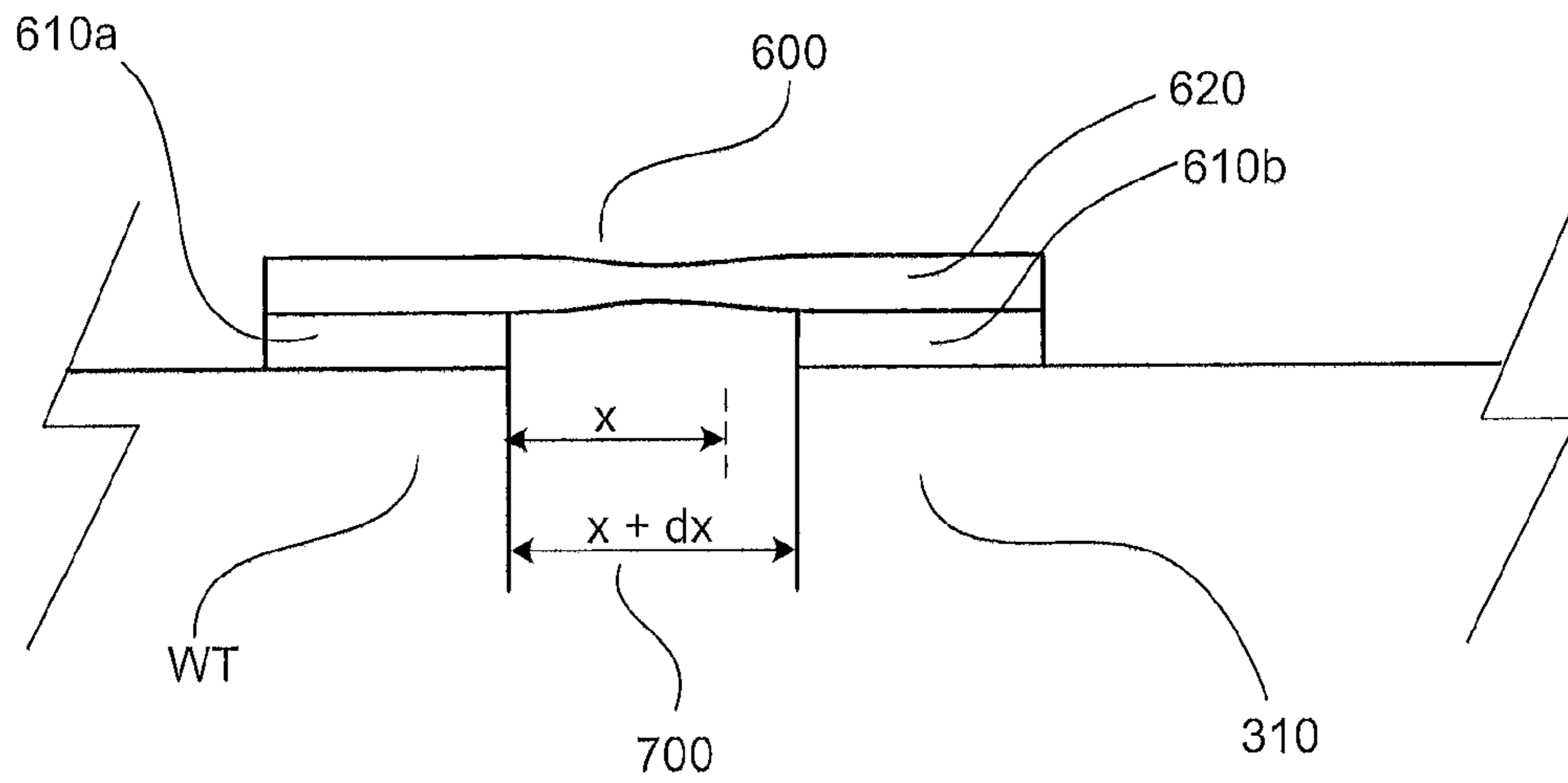
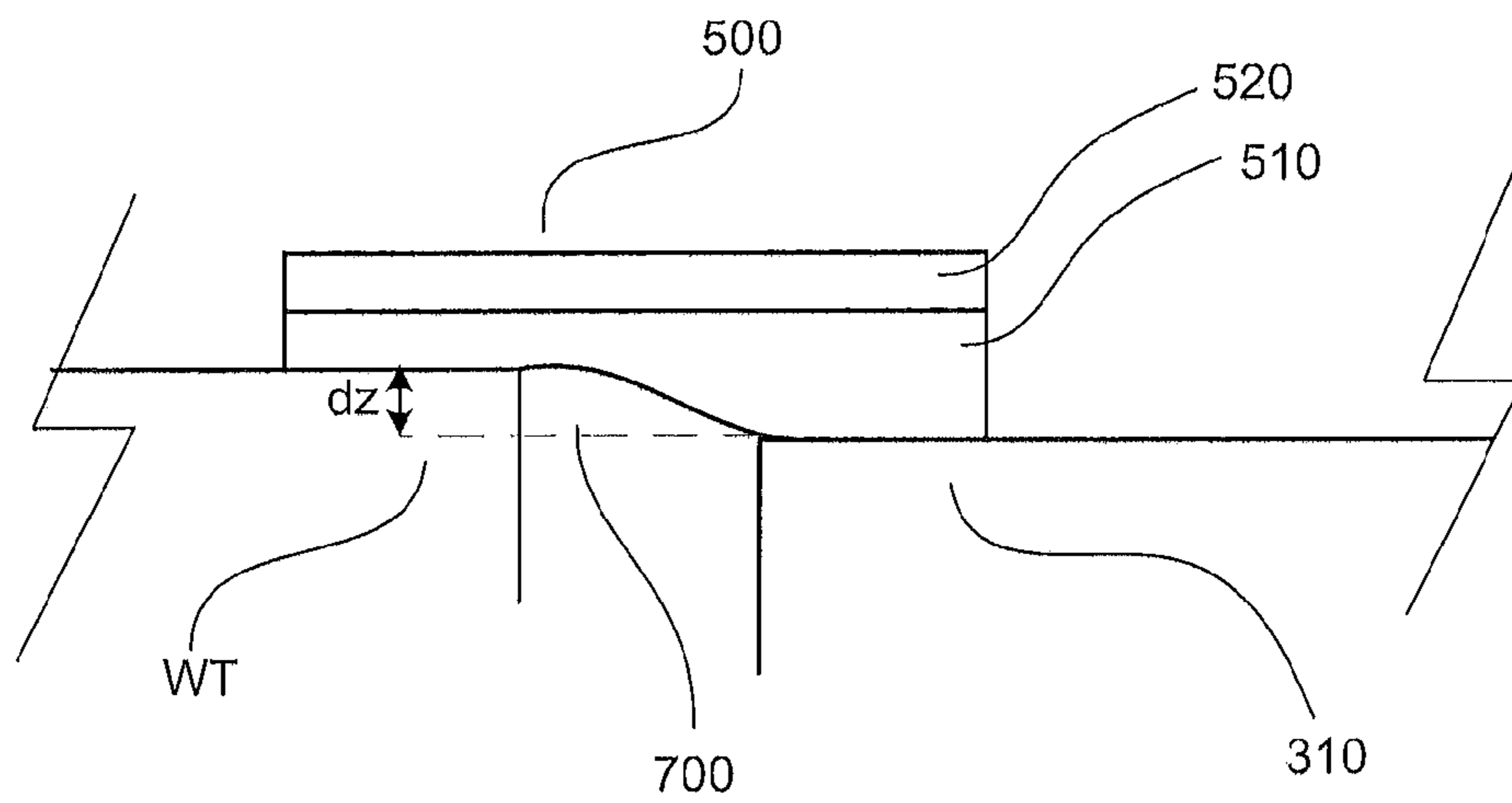


Fig. 16



-- PRIOR ART --

Fig. 17

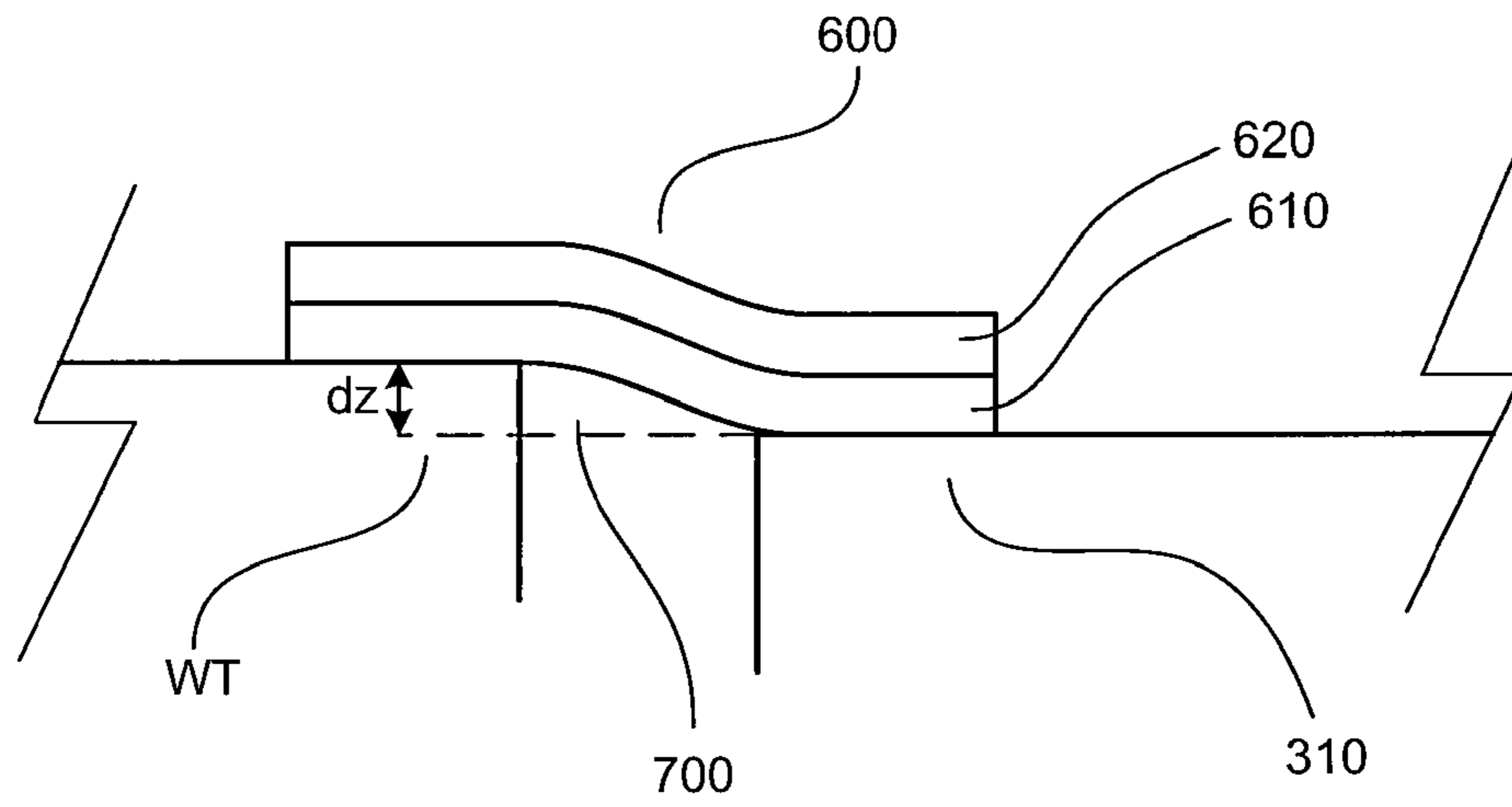


Fig. 18

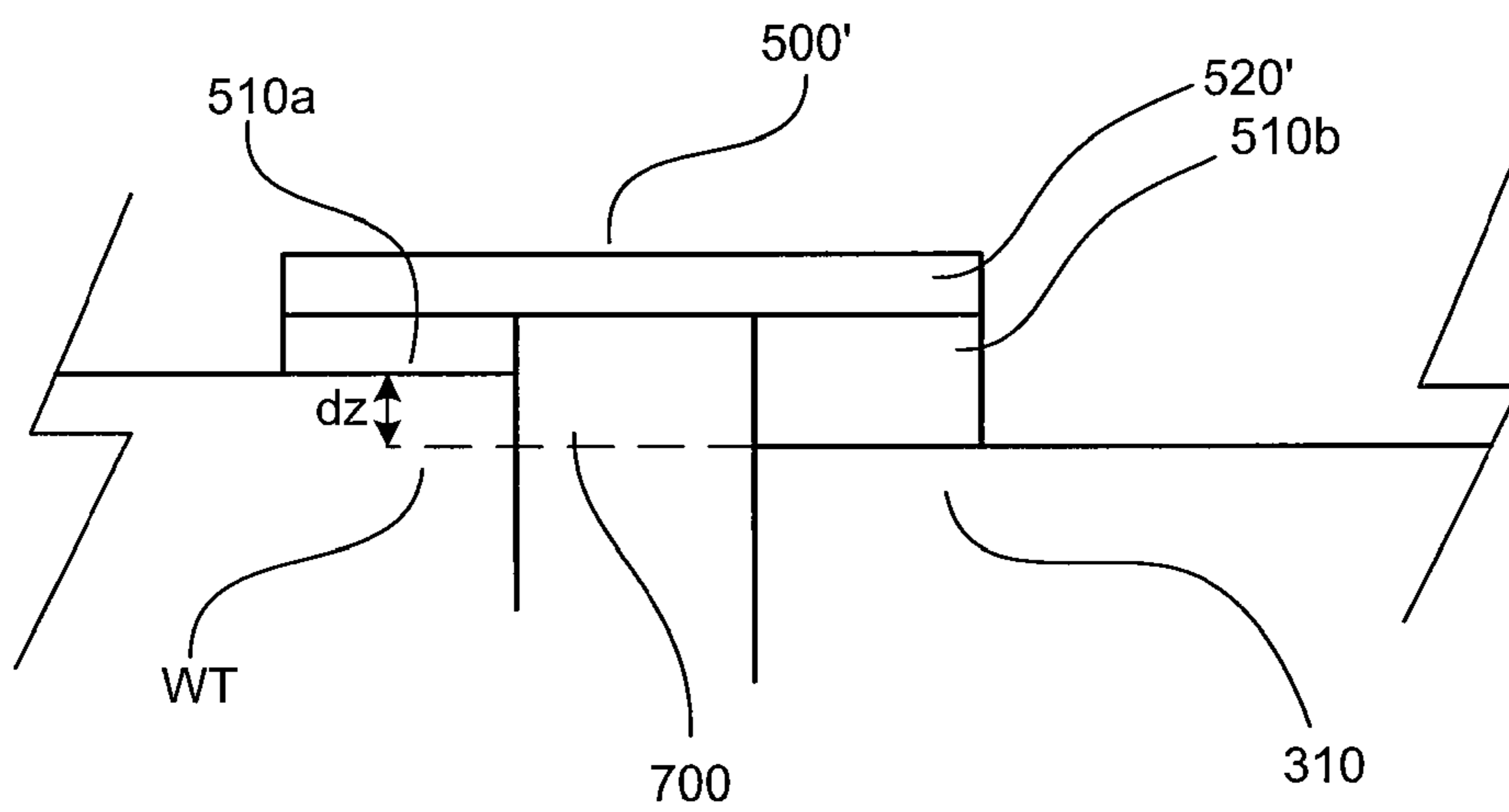


Fig. 19

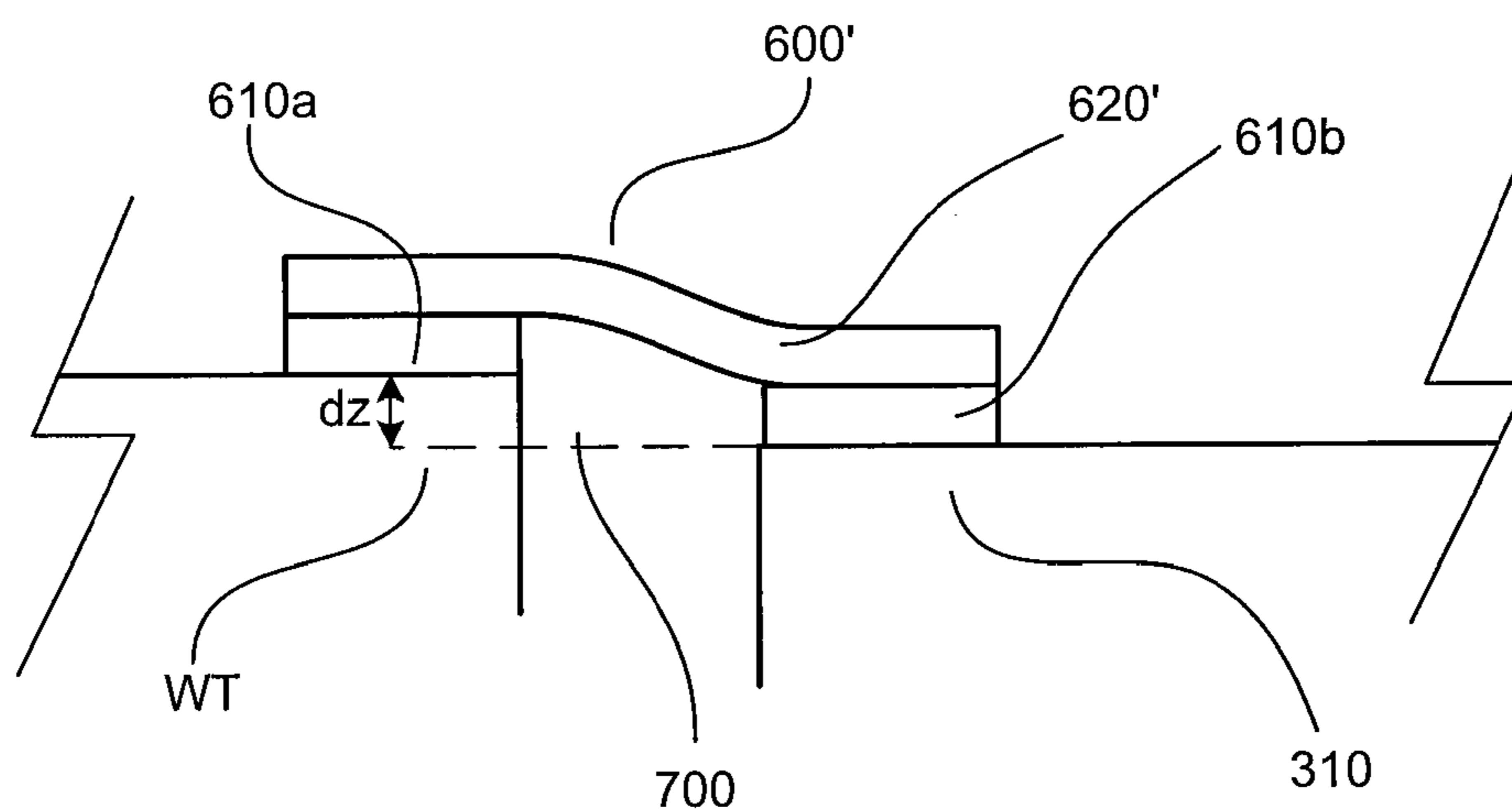


Fig. 20

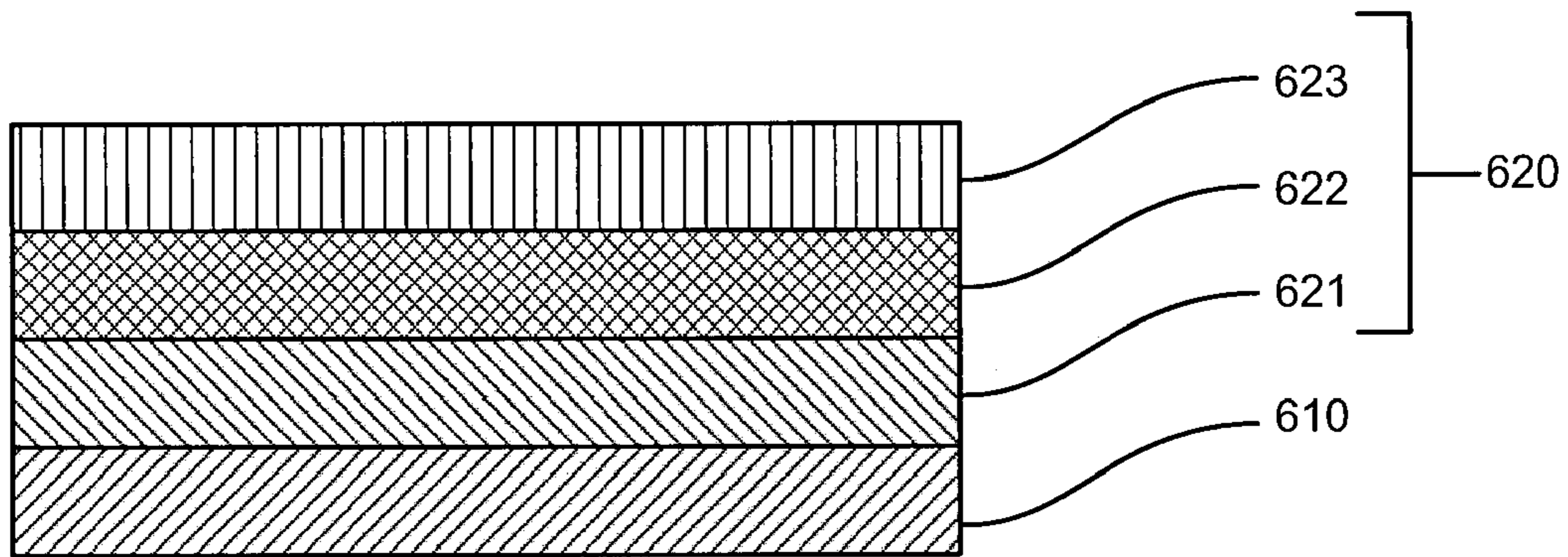


Fig. 21

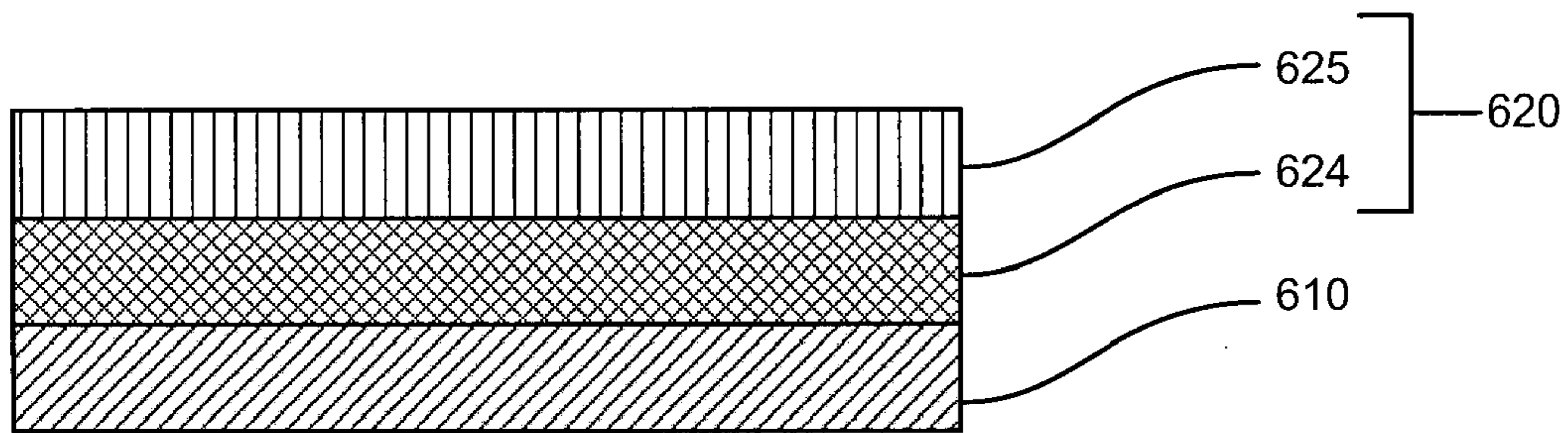


Fig. 22

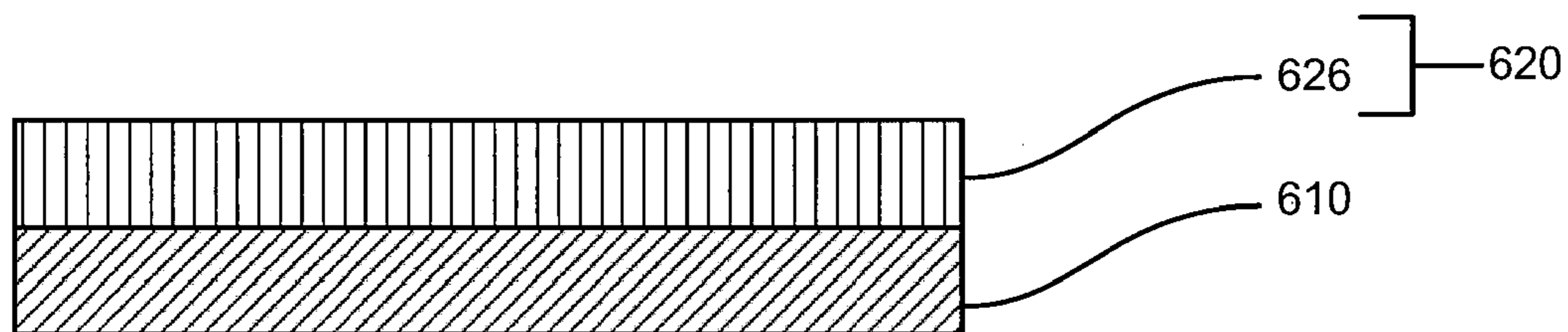


Fig. 23

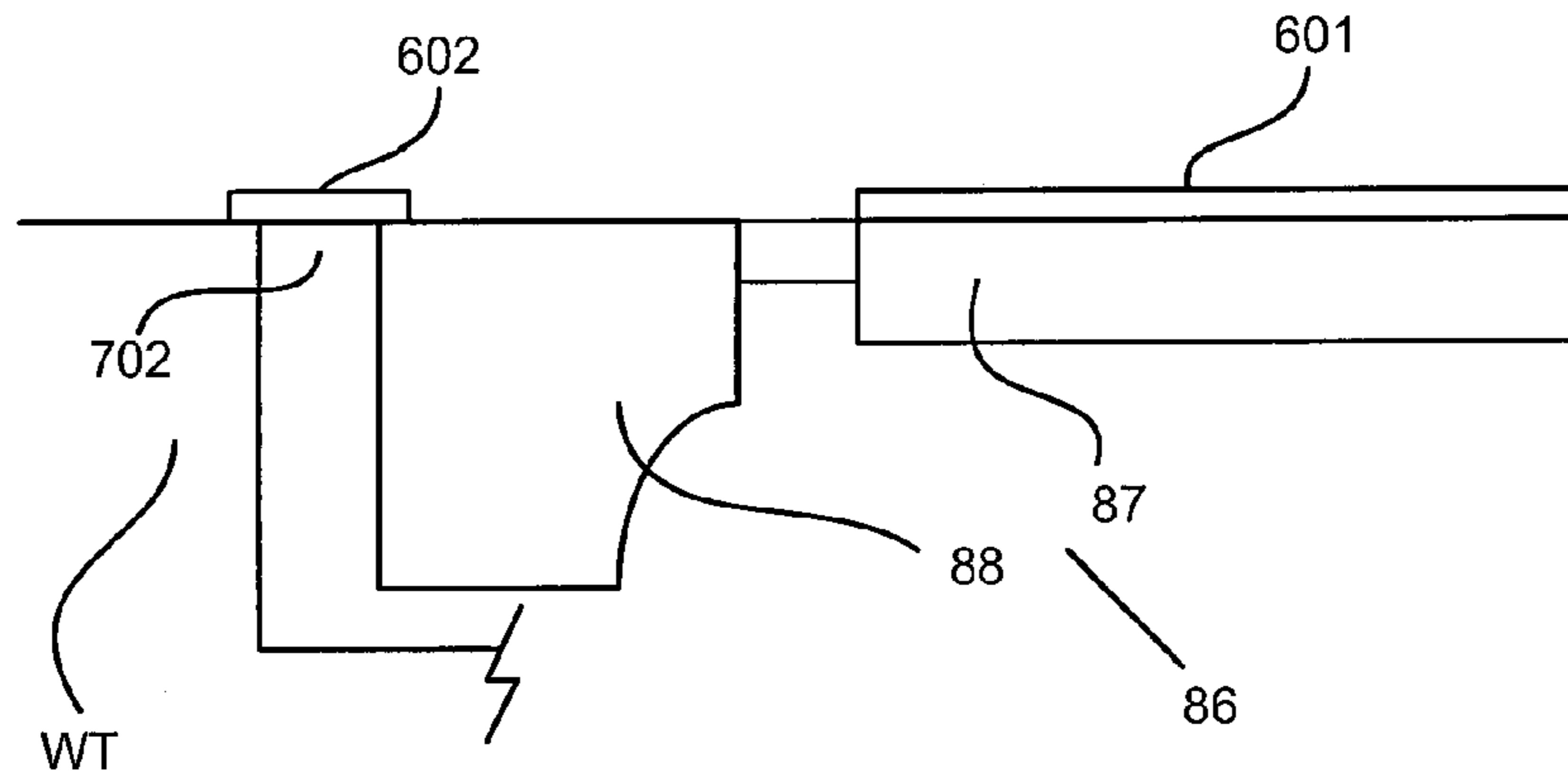


Fig. 24

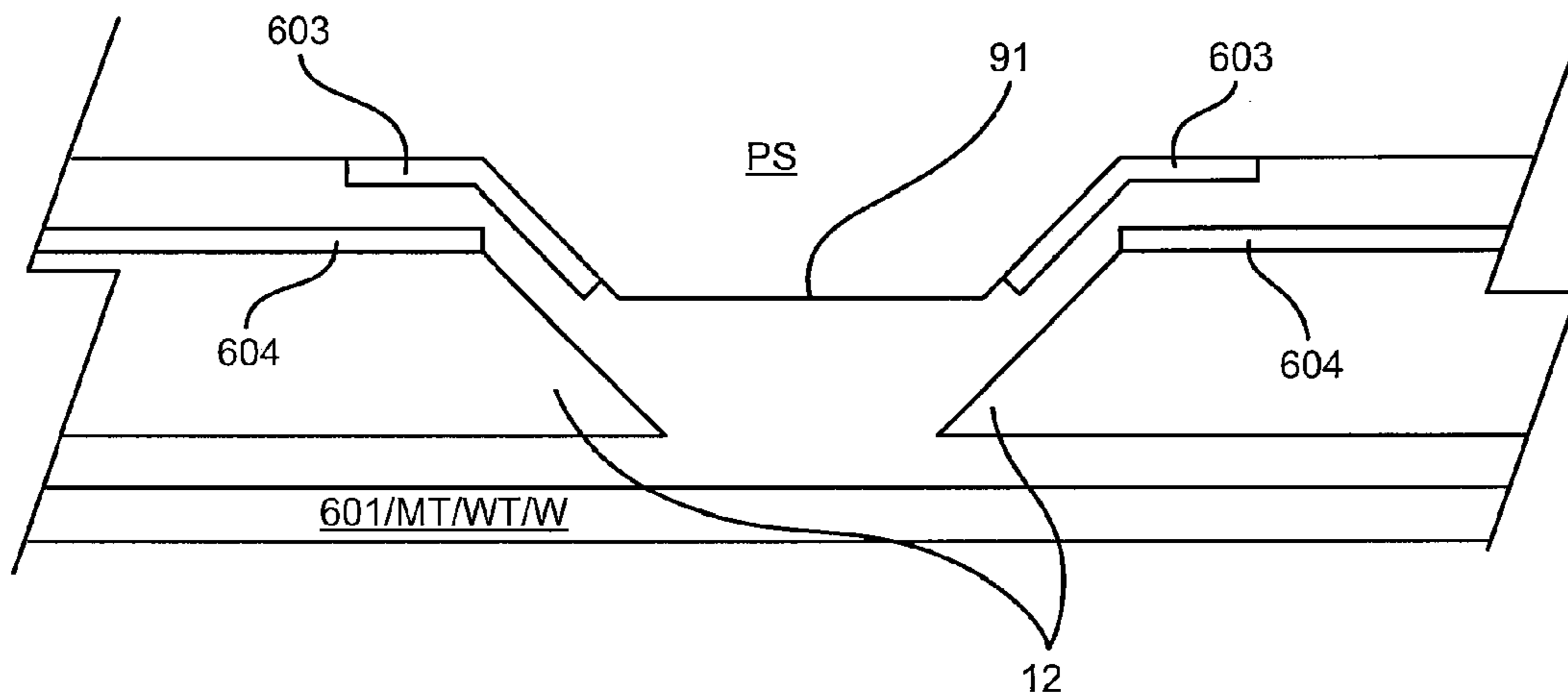


Fig. 25

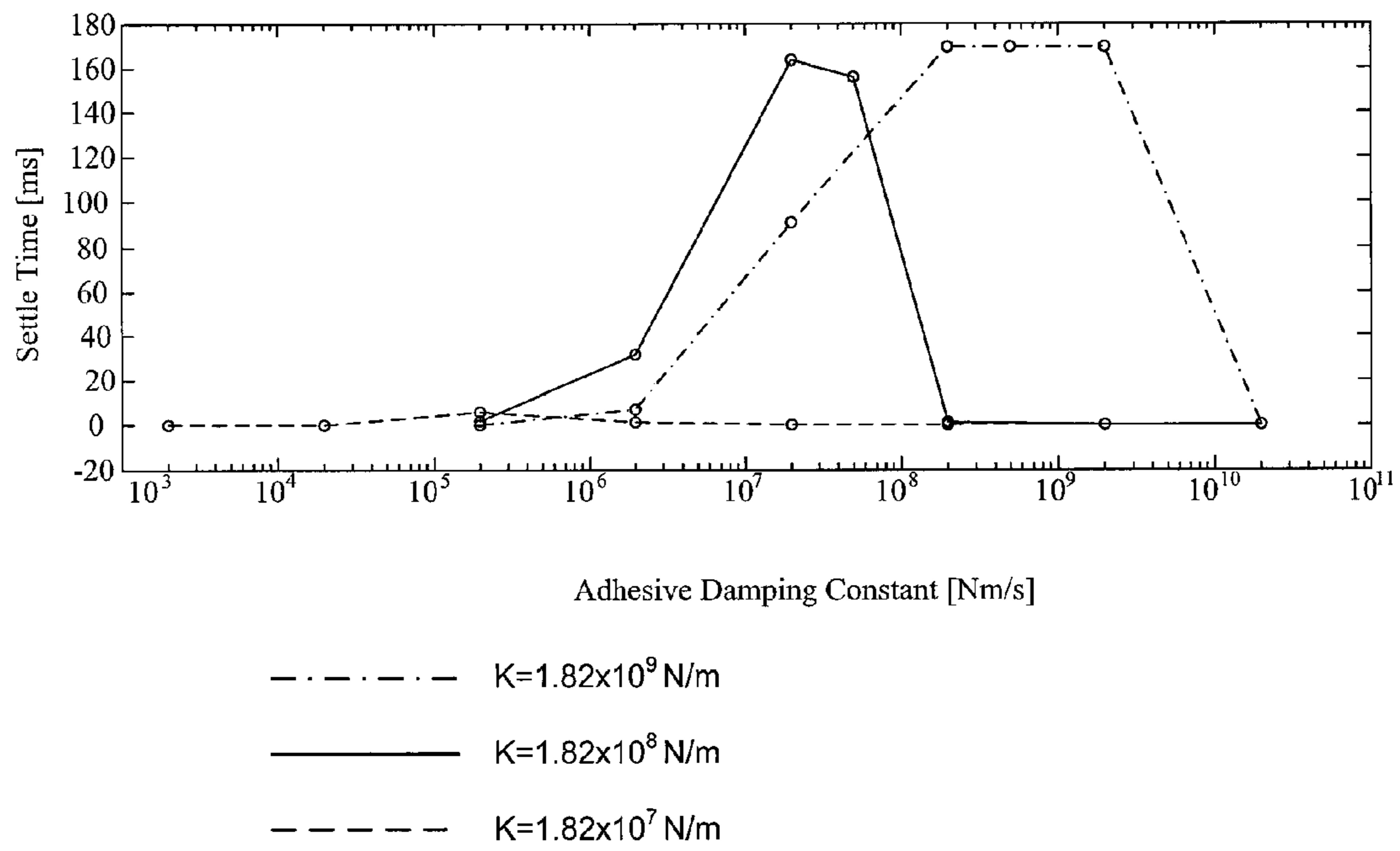


Fig. 26

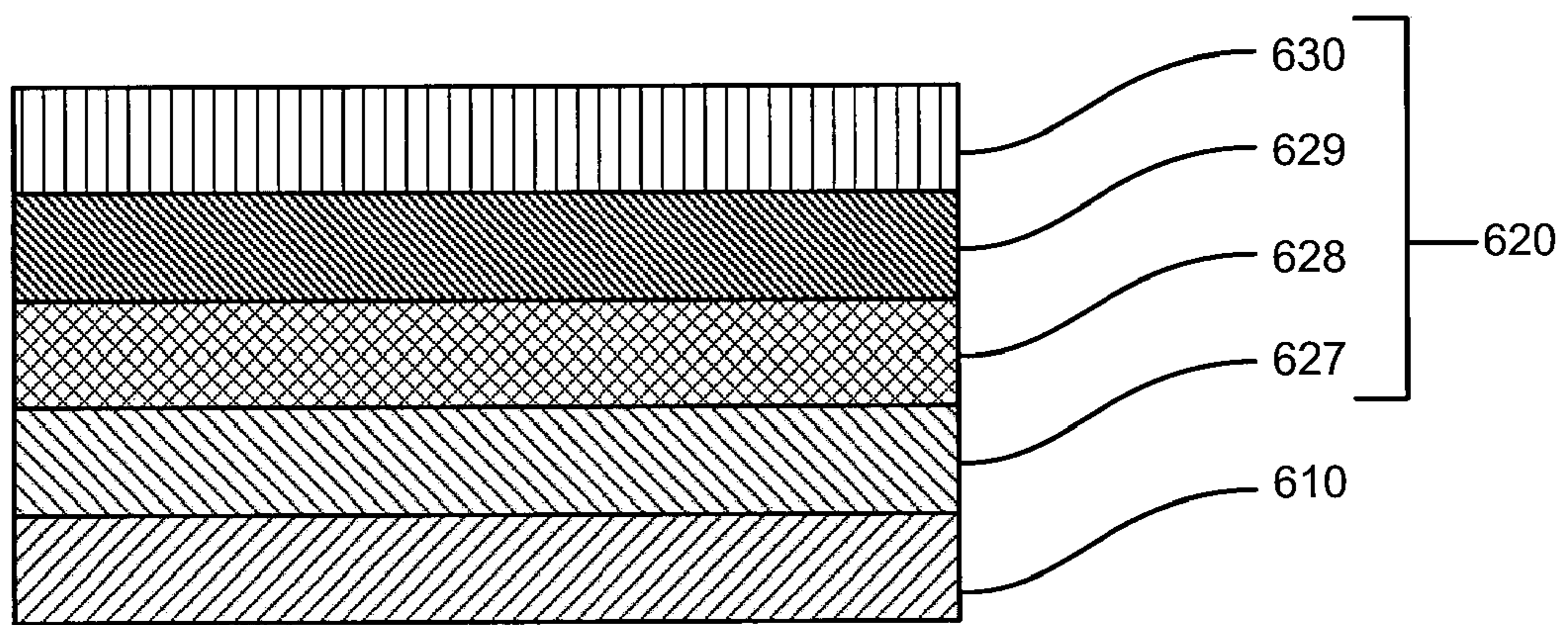


Fig. 27

LITHOGRAPHIC APPARATUS, REMOVABLE MEMBER AND DEVICE MANUFACTURING METHOD

This application claims priority and benefit under 5 U.S.C. §119(e) to U.S. Provisional Patent Application No. 61/261,899, entitled "Lithographic Apparatus, Removable Member and Device Manufacturing Method", filed on Nov. 17, 2009 and to U.S. Provisional Patent Application No. 61/360,850, entitled "Lithographic Apparatus, Removable Member and Device Manufacturing Method", filed on Jul. 1, 2010. The content of each of the foregoing applications is incorporated herein in its entirety by reference.

FIELD

The present invention relates to a lithographic apparatus, a removable member, and a method for applying a removable member to a lithographic apparatus.

BACKGROUND

A lithographic apparatus is a machine that applies a desired pattern onto a substrate, usually onto a target portion of the substrate. A lithographic apparatus can be used, for example, in the manufacture of integrated circuits (ICs). In that instance, a patterning device, which is alternatively referred to as a mask or a reticle, may be used to generate a circuit pattern to be formed on an individual layer of the IC. This pattern can be transferred onto a target portion (e.g. comprising part of, one, or several dies) on a substrate (e.g. a silicon wafer). Transfer of the pattern is typically via imaging onto a layer of radiation-sensitive material (resist) provided on the substrate. In general, a single substrate will contain a network of adjacent target portions that are successively patterned. Known lithographic apparatus include a stepper and a scanner. In a stepper each target portion is irradiated by exposing an entire pattern onto the target portion at one time. In a scanner each target portion is irradiated by scanning the pattern through a radiation beam in a given direction (the "scanning"-direction) while synchronously scanning the substrate parallel or anti-parallel to this direction. It is also possible to transfer the pattern from the patterning device to the substrate by imprinting the pattern onto the substrate.

It has been proposed to immerse the substrate in the lithographic projection apparatus in a liquid having a relatively high refractive index, e.g. water, so as to fill a space between the final element of the projection system and the substrate. In an embodiment, the liquid is distilled water, although another liquid can be used. An embodiment of the invention will be described with reference to liquid. However, another fluid may be suitable, particularly a wetting fluid, an incompressible fluid and/or a fluid with higher refractive index than air, desirably a higher refractive index than water. Fluids excluding gases are particularly desirable. The point of this is to enable imaging of smaller features since the exposure radiation will have a shorter wavelength in the liquid. (The effect of the liquid may also be regarded as increasing the effective numerical aperture (NA) of the system and also increasing the depth of focus.) Other immersion liquids have been proposed, including water with solid particles (e.g. quartz) suspended therein, or a liquid with a nano-particle suspension (e.g. particles with a maximum dimension of up to 10 nm). The suspended particles may or may not have a similar or the same refractive index as the liquid in which they are suspended.

Other liquids which may be suitable include a hydrocarbon, such as an aromatic, a fluorohydrocarbon, and/or an aqueous solution.

Submersing the substrate or substrate and substrate table in a bath of liquid (see, for example, U.S. Pat. No. 4,509,852) means that there is a large body of liquid that must be accelerated during a scanning exposure. This requires additional or more powerful motors and turbulence in the liquid may lead to undesirable and unpredictable effects.

Another arrangement proposed is for a liquid supply system to provide liquid on only a localized area of the substrate and in between the final element of the projection system and the substrate using a liquid confinement system (the substrate generally has a larger surface area than the final element of the projection system). One way which has been proposed to arrange for this is disclosed in WO 99/49504. This type of arrangement may be referred to as a localized immersion system.

Another arrangement is an all wet arrangement in which the immersion liquid is unconfined as disclosed in PCT Patent Application Publication No. WO 2005/064405. In such a system the immersion liquid is unconfined. The whole top surface of the substrate is covered in liquid. This may be advantageous because then the whole top surface of the substrate is exposed to the substantially same conditions. This may have an advantage for temperature control and processing of the substrate. In WO 2005/064405, a liquid supply system provides liquid to the gap between the final element of the projection system and the substrate. That liquid is allowed to leak (or flow) over the remainder of the substrate. A barrier at the edge of a substrate table prevents the liquid from escaping so that it can be removed from the top surface of the substrate table in a controlled way. Although such a system improves temperature control and processing of the substrate, evaporation of the immersion liquid may still occur. One way of helping to alleviate that problem is described in United States Patent Application Publication No. US 2006/0119809. A member is provided which covers the substrate in all positions and which is arranged to have immersion liquid extending between it and the top surface of the substrate and/or substrate table which holds the substrate.

In European Patent Application Publication No. EP 1420300 and United States Patent Application Publication No. US 2004-0136494, each hereby incorporated in their entirety by reference, the idea of a twin or dual stage immersion lithography apparatus is disclosed. Such an apparatus is provided with two tables for supporting a substrate. Leveling measurements are carried out with a table at a first position, without immersion liquid, and exposure is carried out with a table at a second position, where immersion liquid is present. Alternatively, the apparatus has only one table.

After exposure of a substrate in an immersion lithographic apparatus, the substrate table may be moved away from its exposure position to a position in which the substrate may be removed and replaced by a different substrate. This is known as substrate swap. In a two stage lithographic apparatus, a swap of the tables may take place under the projection system.

In an immersion apparatus, immersion fluid is handled by a fluid handling system or apparatus. In an embodiment the fluid handling system may supply immersion fluid and therefore be a fluid supply system. In an embodiment the fluid handling system may at least partly confine immersion fluid and thereby be a fluid confinement system. In an embodiment the fluid handling system may provide a barrier to immersion fluid and thereby be a barrier member, such as a fluid confinement structure. In an embodiment the fluid handling system may create or use a flow of fluid (such as gas), for

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example to help in handling liquid, e.g. in controlling the flow and/or the position of the immersion fluid. The flow of gas may form a seal to confine the immersion fluid so the fluid handling structure may be referred to as a seal member; such a seal member may be a fluid confinement structure. In an embodiment, immersion liquid is used as the immersion fluid. In that case the fluid handling system may be a liquid handling system. The fluid handling system may be located between the projection system and the substrate table. In reference to the aforementioned description, reference in this paragraph to a feature defined with respect to fluid may be understood to include a feature defined with respect to liquid, if the context is deemed appropriate.

SUMMARY

In an immersion lithographic apparatus, a gap may exist in a surface of an immersion system (e.g. a part of the lithographic apparatus which contacts immersion liquid). For example, the gap may be between different components or between different parts of the same component. It is desirable, for example, to ensure that immersion liquid does not enter the gap. Liquid which escapes into the gap may deleteriously affect the performance of the immersion system, and so the immersion lithographic apparatus. Therefore it is desirable that the gap is liquidproofed against ingress of immersion liquid.

It is desirable, for example, to provide a sealing member for sealing a gap in an immersion lithographic apparatus, for example a surface in an immersion system. As some features of the immersion system, for example a substrate table and a projection system, may undergo rapid acceleration with respect to each other a force may be applied between the different components of the immersion system, for example the parts forming the gap. An applied force may cause relative movement therebetween. However, where the relative position of the two components, such as an optical sensor and a table, needs to be accurately known, for example for exposing a target portion, it is desirable for the components to have a similar, if not the same, relative position before and after the application of the force. Therefore it is desirable, for example, to provide a sealing member that does not have significant force coupling, in particular time-related force-coupling, between the parts of the immersion lithographic apparatus which form the sealed gap.

According to an aspect, there is provided a sealing member kit for sealing a gap formed between at least two surfaces of an immersion lithographic apparatus from immersion liquid ingress, the sealing member kit for forming a sealing member, the sealing member kit comprising:

- a plastic material or polymeric sealing portion; and
 - an adhesive to attach the sealing portion to a surface of an immersion lithographic apparatus,
- wherein the stiffness of the plastic material or polymeric sealing portion is no more than 100% of the stiffness of the adhesive.

BRIEF DESCRIPTION OF THE DRAWINGS

Embodiments of the invention will now be described, by way of example only, with reference to the accompanying schematic drawings in which corresponding reference symbols indicate corresponding parts, and in which:

FIG. 1 depicts a lithographic apparatus according to an embodiment of the invention;

FIGS. 2 and 3 depict a liquid supply system for use in a lithographic projection apparatus;

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FIG. 4 depicts a further liquid supply system for use in a lithographic projection apparatus;

FIG. 5 depicts a further liquid supply system for use in a lithographic projection apparatus;

FIG. 6 depicts, in plan, a substrate table;

FIG. 7 depicts, in plan, a measurement table;

FIG. 8 depicts, in plan, a removable member of an embodiment of the invention in the form of a sealing member;

FIG. 9 depicts, in cross-section, a sealing member sealing a gap between two surfaces of an immersion lithographic apparatus such as a sensor and a surface of a table which holds the sensor;

FIG. 10 depicts, in cross-section, a sealing member after movement, in a plane substantially parallel to the plane of the sealing member or the table, of at least one of the components forming the gap which the sealing member seals;

FIG. 11 depicts, in cross-section, a sealing member according to an embodiment of the invention sealing a gap between two surfaces of an immersion lithographic apparatus;

FIG. 12 depicts, in cross-section, the sealing member of FIG. 11 after movement, in a plane substantially parallel to the plane of the sealing member or the table, of at least one of the components forming the gap which the sealing member seals;

FIG. 13 depicts, in cross-section, a sealing member sealing a gap between two surfaces of an immersion lithographic apparatus such as a sensor provided in a table of FIG. 6 or FIG. 7 and the surface of the table;

FIG. 14 depicts, in cross-section, the sealing member shown FIG. 13 after movement, in a plane substantially parallel to the plane of the sealing member or the table, of at least one of the components forming the gap which the sealing member seals;

FIG. 15 depicts, in cross-section, a sealing member according to an embodiment of the invention sealing a gap between two surfaces of an immersion lithographic apparatus;

FIG. 16 depicts, in cross-section, the sealing member of FIG. 15 after movement of at least one of the surfaces sealed by the sealing member;

FIG. 17 depicts, in cross-section, the sealing member of FIG. 9 after movement, in a direction perpendicular to the plane of the sealing member, of at least one of the components forming the gap sealed by the sealing member;

FIG. 18 depicts, in cross-section, the sealing member of FIG. 11 after movement, in a direction perpendicular to the plane of the sealing member, of at least one of the components forming the gap sealed by the sealing member;

FIG. 19 depicts, in cross-section, the sealing member of FIG. 13 after movement, in a direction perpendicular to the plane of the sealing member, of at least one of the components forming the gap sealed by the sealing member;

FIG. 20 depicts, in cross-section, the sealing member of FIG. 15 after movement, in a direction perpendicular to the plane of the sealing member, of at least one of the components forming the gap sealed by the sealing member;

FIG. 21 is a schematic representation of a cross-section along line 9-9 of FIG. 8, through a removable member according to an embodiment of the invention;

FIG. 22 is a schematic representation of a cross-section along line 9-9 of FIG. 8, through a removable member according to an embodiment of the invention;

FIG. 23 is a schematic representation of a cross-section along line 9-9 of FIG. 8, through a removable member according to an embodiment of the invention;

FIG. 24 depicts, in cross section, a swap bridge for engagement to a substrate table WT, indicating possible positions of a surface member;

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FIG. 25 depicts, in cross section, a final element of a projection system and a liquid containment structure, indicating possible positions of a surface member;

FIG. 26 is a graph showing the effect of adhesive damping constant and sealing portion stiffness on the settling time of a sealing member; and

FIG. 27 is a schematic representation of a cross-section along line 9-9 of FIG. 8, through a removable member according to an embodiment of the invention.

DETAILED DESCRIPTION

FIG. 1 schematically depicts a lithographic apparatus according to one embodiment of the invention. The apparatus comprises:

- an illumination system (illuminator) IL configured to condition a radiation beam B (e.g. UV radiation or DUV radiation).
- a support structure (e.g. a mask table) MT constructed to support a patterning device (e.g. a mask) MA and connected to a first positioner PM configured to accurately position the patterning device MA in accordance with certain parameters;
- a substrate table (e.g. a wafer table) WT constructed to hold a substrate (e.g. a resist-coated wafer) W and connected to a second positioner PW configured to accurately position the substrate W in accordance with certain parameters; and
- a projection system (e.g. a refractive projection lens system) PS configured to project a pattern imparted to the radiation beam B by patterning device MA onto a target portion C (e.g. comprising one or more dies) of the substrate W.

The illumination system may include various types of optical components, such as refractive, reflective, magnetic, electromagnetic, electrostatic or other types of optical components, or any combination thereof, for directing, shaping, or controlling radiation.

The support structure MT holds the patterning device. It holds the patterning device in a manner that depends on the orientation of the patterning device, the design of the lithographic apparatus, and other conditions, such as for example whether or not the patterning device is held in a vacuum environment. The support structure can use mechanical, vacuum, electrostatic or other clamping techniques to hold the patterning device. The support structure may be a frame or a table, for example, which may be fixed or movable as required. The support structure may ensure that the patterning device is at a desired position, for example with respect to the projection system. Any use of the terms “reticle” or “mask” herein may be considered synonymous with the more general term “patterning device.”

The term “patterning device” used herein should be broadly interpreted as referring to any device that can be used to impart a radiation beam with a pattern in its cross-section such as to create a pattern in a target portion of the substrate. It should be noted that the pattern imparted to the radiation beam may not exactly correspond to the desired pattern in the target portion of the substrate, for example if the pattern includes phase-shifting features or so called assist features. Generally, the pattern imparted to the radiation beam will correspond to a particular functional layer in a device being created in the target portion, such as an integrated circuit.

The patterning device may be transmissive or reflective. Examples of patterning devices include masks, programmable mirror arrays, and programmable LCD panels. Masks are well known in lithography, and include mask types such as

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binary, alternating phase-shift, and attenuated phase-shift, as well as various hybrid mask types. An example of a programmable mirror array employs a matrix arrangement of small mirrors, each of which can be individually tilted so as to reflect an incoming radiation beam in different directions. The tilted mirrors impart a pattern in a radiation beam which is reflected by the mirror matrix.

The term “projection system” used herein should be broadly interpreted as encompassing any type of projection system, including refractive, reflective, catadioptric, magnetic, electromagnetic and electrostatic optical systems, or any combination thereof, as appropriate for the exposure radiation being used, or for other factors such as the use of an immersion liquid or the use of a vacuum. Any use of the term “projection lens” herein may be considered as synonymous with the more general term “projection system”.

As here depicted, the apparatus is of a transmissive type (e.g. employing a transmissive mask). Alternatively, the apparatus may be of a reflective type (e.g. employing a programmable mirror array of a type as referred to above, or employing a reflective mask).

The lithographic apparatus may be of a type having two (dual stage) or more substrate tables (and/or two or more patterning device tables). In such “multiple stage” machines the additional tables may be used in parallel, or preparatory steps may be carried out on one or more tables while one or more other tables are being used for exposure.

Referring to FIG. 1, the illuminator IL receives a radiation beam from a radiation source SO. The source SO and the lithographic apparatus may be separate entities, for example when the source is an excimer laser. In such cases, the source SO is not considered to form part of the lithographic apparatus and the radiation beam is passed from the source SO to the illuminator IL with the aid of a beam delivery system BD comprising, for example, suitable directing mirrors and/or a beam expander. In other cases the source SO may be an integral part of the lithographic apparatus, for example when the source is a mercury lamp. The source SO and the illuminator IL, together with the beam delivery system BD if required, may be referred to as a radiation system.

The illuminator IL may comprise an adjuster AD for adjusting the angular intensity distribution of the radiation beam. Generally, at least the outer and/or inner radial extent (commonly referred to as σ -outer and σ -inner, respectively) of the intensity distribution in a pupil plane of the illuminator IL can be adjusted. In addition, the illuminator IL may comprise various other components, such as an integrator IN and a condenser CO. The illuminator IL may be used to condition the radiation beam, to have a desired uniformity and intensity distribution in its cross-section.

The radiation beam B is incident on the patterning device MA (e.g., mask), which is held on the support structure MT (e.g., mask table), and is patterned by the patterning device MA. Having traversed the patterning device MA, the radiation beam B passes through the projection system PS, which focuses the beam onto a target portion C of the substrate W. With the aid of the second positioner PW and position sensor IF (e.g. an interferometric device, linear encoder or capacitive sensor), the substrate table WT can be moved accurately, e.g. so as to position different target portions C in the path of the radiation beam B. Similarly, the first positioner PM and another position sensor (which is not explicitly depicted in FIG. 1) can be used to accurately position the patterning device MA with respect to the path of the radiation beam B, e.g. after mechanical retrieval from a mask library, or during a scan. In general, movement of the support structure MT may be realized with the aid of a long-stroke module (coarse

positioning) and a short-stroke module (fine positioning), which form part of the first positioner PM. Similarly, movement of the substrate table WT may be realized using a long-stroke module and a short-stroke module, which form part of the second positioner PW. In the case of a stepper (as opposed to a scanner) the support structure MT may be connected to a short-stroke actuator only, or may be fixed. Patterning device MA and substrate W may be aligned using patterning device alignment marks M1, M2 and substrate alignment marks P1, P2. Although the substrate alignment marks as illustrated occupy dedicated target portions, they may be located in spaces between target portions (these are known as scribe-lane alignment marks). Similarly, in situations in which more than one die is provided on the patterning device MA, the patterning device alignment marks may be located between the dies.

The depicted apparatus could be used in at least one of the following modes:

1. In step mode, the support structure MT and the substrate table WT are kept essentially stationary, while an entire pattern imparted to the radiation beam B is projected onto a target portion C at one time (i.e. a single static exposure). The substrate table WT is then shifted in the X and/or Y direction so that a different target portion C can be exposed. In step mode, the maximum size of the exposure field limits the size of the target portion C imaged in a single static exposure.

2. In scan mode, the support structure MT and the substrate table WT are scanned synchronously while a pattern imparted to the radiation beam B is projected onto a target portion C (i.e. a single dynamic exposure). The velocity and direction of the substrate table WT relative to the support structure MT may be determined by the (de-)magnification and image reversal characteristics of the projection system PS. In scan mode, the maximum size of the exposure field limits the width (in the non-scanning direction) of the target portion C in a single dynamic exposure, whereas the length of the scanning motion determines the height (in the scanning direction) of the target portion C.

3. In another mode, the support structure MT is kept essentially stationary holding a programmable patterning device, and the substrate table WT is moved or scanned while a pattern imparted to the radiation beam B is projected onto a target portion C. In this mode, generally a pulsed radiation source is employed and the programmable patterning device is updated as required after each movement of the substrate table WT or in between successive radiation pulses during a scan. This mode of operation can be readily applied to maskless lithography that utilizes programmable patterning device, such as a programmable mirror array of a type as referred to above.

Combinations and/or variations on the above described modes of use or entirely different modes of use may also be employed.

Arrangements for providing liquid between a final element of the projection system and the substrate can be classed into at least three general categories. These are the bath type arrangement, the so-called localized immersion system and the all-wet immersion system. In the bath type arrangement substantially the whole of the substrate and optionally part of the substrate table is submersed in a bath of liquid.

The localized immersion system uses a liquid supply system in which liquid is only provided to a localized area of the substrate. The space filled by liquid is smaller in plan than the top surface of the substrate and the area filled with liquid remains substantially stationary relative to the projection system PS while the substrate moves underneath that area. FIGS. 2-5 show different supply devices which can be used in such

a system. Sealing features are present to seal liquid to the localized area. One way which has been proposed to arrange for this is disclosed in PCT Patent Application Publication No. WO 99/49504.

In the all wet arrangement the liquid is unconfined. Substantially the whole top surface of the substrate and all or part of the substrate table is covered in immersion liquid. The depth of the liquid covering at least the substrate is small. The liquid may be a film, such as a thin film, of liquid on the substrate. Immersion liquid may be supplied to or in the region of a projection system and a facing surface facing the projection system (such a facing surface may be the surface of a substrate and/or a substrate table). Any of the liquid supply devices of FIGS. 2-5 may be used in such a system. However, sealing features may not be present, may not be activated, may not be as efficient as normal or may be otherwise ineffective to seal liquid to only the localized area.

As illustrated in FIGS. 2 and 3, liquid is supplied by at least one inlet onto the substrate, preferably along the direction of movement of the substrate relative to the final element. Liquid is removed by at least one outlet after having passed under the projection system PS. That is, as the substrate is scanned beneath the element in a $-X$ direction, liquid is supplied at the $+X$ side of the element and taken up at the $-X$ side. FIG. 2 shows the arrangement schematically in which liquid is supplied via inlet and is taken up on the other side of the element by outlet which is connected to a low pressure source. In the illustration of FIG. 2 the liquid is supplied along the direction of movement of the substrate W relative to the final element, though this does not need to be the case. Various orientations and numbers of in- and out-lets positioned around the final element are possible; one example is illustrated in FIG. 3 in which four sets of an inlet with an outlet on either side are provided in a regular pattern around the final element. Note that the direction of flow of the liquid is shown by arrows in FIGS. 2 and 3.

A further immersion lithography solution with a localized liquid supply system is shown in FIG. 4. Liquid is supplied by two groove inlets on either side of the projection system PS. Liquid is removed by a plurality of discrete outlets arranged radially outwardly of the inlets. The inlets can be arranged in a plate with a hole in its center and through which the projection beam is projected. Liquid is supplied by one groove inlet on one side of the projection system PS and removed by a plurality of discrete outlets on the other side of the projection system PS, causing a flow of a thin film of liquid between the projection system PS and the substrate W. The choice of which combination of inlet and outlets to use can depend on the direction of movement of the substrate W (the other combination of inlet and outlets being inactive). Note that the direction of flow of fluid and of the substrate W is shown by arrows in FIG. 4.

Another arrangement which has been proposed is to provide the liquid supply system with liquid confinement structure which extends along at least a part of a boundary of the space between the final element of the projection system and the substrate table. Such an arrangement is illustrated in FIG. 5.

FIG. 5 schematically depicts a localized liquid supply system or fluid handling structure with a liquid confinement structure 12, which extends along at least a part of a boundary of the space 11 between the final element of the projection system PS and a facing surface (e.g. of a table, such as substrate table WT, or a substrate W which may be supported by the substrate table. The table may have a cover plate which may serve as the facing surface). (Please note that reference in the following text to the surface of the substrate W also refers

in addition or in the alternative to a surface of the substrate table WT, unless expressly stated otherwise.) The liquid confinement structure **12** may be substantially stationary relative to the projection system PS in the XY plane. The liquid confinement structure **12** may move relative to the projection system in the Z direction (e.g. in the direction of the optical axis). In an embodiment, a seal is formed between the liquid confinement structure **12** and the facing surface. The seal may be a contactless seal such as a gas seal (such a system with a gas seal is disclosed in United States Patent Application Publication No. US 2004-0207824) or liquid seal.

The liquid confinement structure **12** at least partly contains liquid in the space **11** between a final element of the projection system PS and the substrate W. A contactless seal, such as a gas seal **16**, to the substrate W may be formed around the image field of the projection system PS so that liquid is confined within the space **11** between the substrate W surface and the final element of the projection system PS. The space **11** is at least partly formed by the liquid confinement structure **12** positioned below and surrounding the final element of the projection system PS. Liquid is brought into the space **11** below the projection system PS and within the liquid confinement structure **12** by liquid inlet **13**. The liquid may be removed by liquid outlet **13**. The liquid confinement structure **12** may extend a little above the final element of the projection system PS. The liquid level rises above the final element so that a buffer of liquid may be provided. In an embodiment, the liquid confinement structure **12** has an inner periphery that at the upper end closely conforms to the shape of the projection system PS or the final element thereof and may, e.g., be round. At the bottom, the inner periphery closely conforms to the shape of the image field, e.g., rectangular, though this need not be the case.

The liquid may be contained in the space **11** by the contactless seal, e.g. gas seal **16**, which, during use, may be formed between the bottom of the liquid confinement structure **12** and the surface of the substrate W. The gas seal **16** is formed by gas, e.g. air or synthetic air but, in an embodiment, N₂ or another inert gas. The gas in the gas seal **16** is provided under pressure via inlet **15** to the gap between liquid confinement structure **12** and substrate W. The gas is extracted via outlet **14**. The overpressure on the gas inlet **15**, vacuum level on the outlet **14** and geometry of the gap are arranged so that there is a high-velocity gas flow inwardly that confines the liquid. The force of the gas on the liquid between the liquid confinement structure **12** and the substrate W contains the liquid in a space **11**. The inlets/outlets may be annular grooves which surround the space **11**. The annular grooves may be continuous or discontinuous. The flow of gas is effective to contain the liquid in the space **11**. Such a system is disclosed in United States Patent Application Publication No. US 2004-0207824, which is hereby incorporated by reference in its entirety. In another embodiment, the liquid confinement structure **12** does not have a gas seal.

The example of FIG. **5** may be a liquid confinement structure used in a localized immersion system or an all wet system as described herein.

The liquid confinement structure **12** of FIG. **5** may have other features. For example, the undersurface **40** of the liquid confinement structure **12** may have an extractor, for example a porous member. The extractor may be an extractor assembly radially inwardly of the outlet **14**. The extractor assembly may extract liquid from between the liquid confinement structure **12** and the substrate W. The extractor assembly may operate as a single phase or as a dual phase extractor. The extractor assembly may comprise a liquid removal device or extractor or inlet such as the one disclosed in United States

Patent Application Publication No. US 2006-0038968, incorporated herein in its entirety by reference. In an embodiment, the extractor comprises an inlet which is covered in a porous material which is used to separate liquid from gas to enable single-liquid phase liquid extraction. The menisci formed in the holes of the porous material prevent ambient gas from being drawn into a chamber of the extractor assembly. When the surface of the porous material comes into contact with liquid there is no meniscus to restrict flow. The liquid can flow freely into the chamber of the liquid removal device. In an embodiment, porous material is at least slightly liquidphilic with respect to the immersion liquid, e.g. water.

An arrangement in which such an extractor assembly is used in combination with a recess and a gas knife is disclosed in detail in United States Patent Application Publication No. US 2006/0158627 incorporated herein in its entirety by reference. An example of an embodiment of a liquid confinement structure suitable for use in an all wet embodiment can be found in United States Patent Application Publication No. 2010/0060868.

An embodiment of liquid confinement structure for example as shown in FIG. **5** has features of a gas drag liquid confinement structure such as that described in U.S. Patent Application Ser. No. 61/181,158 filed 26 May 2009, which is hereby incorporated in its entirety by reference. United States Patent Application Publication No. US 2008/0212046 provides further details and its content is also hereby incorporated by reference in its entirety. Such a gas drag liquid confinement structure is used to remove liquid from between the liquid confinement structure **12** and the facing surface. It may be used instead of a porous member. The features of a gas drag liquid confinement structure include a plurality of openings formed in the undersurface of a confinement structure **12**, around the periphery of the space **11**. The openings are connected to an underpressure source so that liquid is removed from under the liquid confinement structure. The liquid forms a meniscus between the openings and the facing surface. The meniscus is as such pinned by the openings. Liquid may be removed through the openings in two phase. Such a confinement structure may have a gas seal to facilitate the removal of the liquid, the pinning of the meniscus to the openings or both.

In all of the above liquid confinement structures, liquid is supplied to a space **11** between the projection system PS and the facing surface. In the example of FIG. **5** the liquid is supplied through opening **13**, so that it may serve as an inlet. Liquid may be removed from the space. In an embodiment immersion liquid is removed through an opening in the liquid confinement structure **12**, for example opening **13**, so that it serves as an outlet. Liquid may be supplied through an opening **13** and removed from the same opening on the opposite side of the space.

FIG. **6** illustrates a plan view of a top surface of a substrate table WT. In the top surface of the substrate table WT are formed various openings. The top surface of the substrate table WT may otherwise be substantially planar, for example in an axis perpendicular to the optical axis of the projection system. The substrate table WT may comprise a substrate support **80** for supporting a substrate W. The substrate support may be in a recess in the substrate table, for example in a top surface of the substrate table. The recess may be an opening in the top surface of the substrate table, for example as shown as a circular opening in FIG. **6**. The recess may be dimensioned so that when a substrate is supported by the substrate support **80**, the surface of the substrate facing away from the substrate support **80** is substantially co-planar with at least the surrounding surface of the substrate table WT.

The lithographic apparatus may have an interferometer system configured to determine the position of the substrate table WT, and therefore the substrate W (when supported by the substrate table WT). In an embodiment the substrate table WT may have a part of the interferometer system, for example one or more mirrors. The interferometer system may use radiation that is substantially in the plane of the surface of the substrate table WT, for example perpendicular to the optical axis of the lithographic apparatus, to calculate and determine the position of the substrate W. The interferometer system may determine the position of the substrate table WT and/or substrate W relative to another frame of reference, for example, the projection system, or the liquid confinement structure. Additionally or alternatively the lithographic apparatus may comprise an encoder system configured to determine the position of the substrate table WT, and therefore the substrate W (when supported by the substrate table WT). The encoder system may include one or more encoder sensors and one or more encoder blocks which may take the form of a grid that may be provided a graduated scale for accurate positioning. In an embodiment the substrate table WT may have a part of the encoder system, for example one or more encoder sensors and/or one or more encoder blocks. The encoder system may use radiation that is substantially parallel to the plane of the optical axis of the lithographic apparatus to calculate the position of the substrate table WT and/or substrate W. The encoder system may determine the position of the substrate table WT and/or substrate W relative to another frame of reference, for example, the projection system, or the liquid confinement structure.

In an embodiment, the substrate table WT may further comprise a cover plate. The top surface of the cover plate may form the top surface of the substrate table WT. The cover plate may be separable from the rest of the substrate table WT. The cover plate may have an opening through which a substrate may be placed on the substrate support **80**. The top surface of the cover plate may provide a flat and continuous upper surface to the substrate table.

It is desirable that components of a substrate table WT may be removed to enable, for example in a non-limiting list, replacement, repair or cleaning of one or more components of the table. In an embodiment, the substrate support **80** is removable, without major dismantling (for example, removal) of one or more other components of the substrate table WT. The cover plate (if present) may be removably mounted. When present on the substrate table WT, the cover plate may cover one or more other elements of the substrate table WT. On removal of the cover plate, another element of the substrate table WT protected by the cover plate in use may be serviced.

One or more components may be positioned around the opening for the substrate support **80**. At least one of these components may need to be illuminated by the beam B of the projection system PS during use. One or more of the components may be a sensor. In the example shown in FIG. **6**, there are a number of sensors including two transmission image sensors (TIS) **310**, a spot sensor **330** and an integrated lens interferometer at scanner (ILIAS) **320** sensor. If one or more of these sensors, e.g. optical components, are covered by the cover plate, at least part of the portion of the cover plate covering the sensor is transparent to the radiation detected by the respective sensor.

It is not necessary that the sensors are located in the same table which supports a substrate. FIG. **7** is a schematic representation of two tables, one of which is a substrate table WT and the other of which is a measurement table MRT. The substrate table WT is similar to the substrate table WT of FIG.

6. The substrate table WT has a substrate support **80** which is configured to support a substrate and a positioning system to enable accurate positioning of the substrate table WT, and therefore a supported substrate W, relative to another frame of reference, for example the projection system. In an embodiment the positioning system is an encoder system having one or more sensors and an encoder grid. In an embodiment an encoder grid **85** is arranged around the periphery of the substrate table. One or more encoder sensors may be positioned relative to the encoder grid, for example a base frame, so as to determine the position of the substrate table relative to the projection system. Each additional sensor may be located on the measurement table MRT, for example to minimize the weight of the substrate table WT. The features of the measurement table MRT may be the same as the substrate table WT, but without the feature of a substrate support **80**. The measurement table may have one or more sensors **310**, **320**, **330**. The measurement table may have a cleaning station. Each of the objects (the sensors, the encoder grid, the substrate support, and the cleaning station) may be located in a recess in the table MRT, WT. The surface of at least one of the objects (except at least the substrate support) may be coplanar with at least part of the table MRT, WT surrounding the respective object. In an embodiment, the substrate table WT and/or the measurement table MRT has a cover plate. In an embodiment the substrate table WT and/or the measurement table MRT has a top surface which is an un-removable, fixed component.

In the arrangements shown in each of FIGS. **6** and **7**, it is desirable for there to be a good seal between the top surface of a table WT, MRT and an object located in an opening in the table MRT, WT, such as at least one of the sensors **310**, **320**, **330**, the encoder grid **85** and the substrate support **80**. It is desirable to have a good seal between an object and the surface of the table surrounding the object to prevent or reduce ingress of immersion liquid into a gap formed between the object and the table. Ingress of immersion liquid may be detrimental to the performance of the immersion lithographic apparatus. The liquid may damage one or more components, for example a delicate component such as a sensor, which may be fluidly connected to the gap for example if the gap is not sealed. Liquid in the gap may transport contamination into the gap, increasing the contamination within the gap. The contamination may be in the form of a particle, for example of a substrate coating. The contamination may be a non-volatile component of the immersion liquid, such as silica, which may remain after the liquid evaporates. The contamination may later be a source of imaging defectivity. On evaporating, the immersion liquid absorbs heat from its surroundings, distorting for example the surfaces forming the gap. Such distortion, for example on a sensor or a substrate support, may affect positioning information, affecting the accurate positioning of a beam onto a target portion of a substrate or sensor.

An embodiment of a sealing member **600** according to an embodiment of the invention is illustrated in plan in FIG. **8**. The sealing member **600** may be removable, so that the sensor can be removed and optionally replaced on the table MRT, WT. In an embodiment, the sealing member **600** may be reused. The sealing member **600** may be disposable. As can be seen, the sealing member **600** is made as a closed loop which has a similar shape as a sensor **310**, **320**, **330** (or other object such as an encoder grid **85** and/or a substrate support **80**) in substantially the same plane as the top surface of the table WT, MRT. The top surface of the table has an opening of similar shape to the sensor in the plane of the top surface of the table; the opening is dimensioned for the object to be placed therein. There may be a gap formed therebetween. The seal-

ing member **600** has an internal periphery which is smaller than the shape of the supported object in the plane of the top surface of the table. The sealing member **600** has an external periphery which is larger than the shape of the opening. The sealing member **600** therefore has a width d , between the internal and external peripheries. In an embodiment the width d is of the order of 10 mm, although a range of from 0.2 mm to 50 mm is possible. Therefore, when the object is placed in the opening, and the sealing member **600** is placed around the periphery of the object, the sealing member **600** covers a portion of the object at its periphery, a part of the table MRT, WT around the opening and the gap formed therebetween.

Although the description herein generally relates in parts to a sealing member **600** for sealing the space, or gap, between an object such as a sensor **310**, **320**, **330** and the top surface of a table WT, MRT, it will be understood that a member similar to a sealing member may be used to seal the space, or gap, between any other two components of an immersion lithographic apparatus where it is desirable to prevent or reduce immersion liquid ingress. The sealing member **600** according to such embodiments may have a shape in plan view (i.e. the view of FIG. **8**) adapted according to (for example corresponding to, or the same as) the shape of the gap to be sealed. For example, a sensor (such as a spot, TIS or ILIAS sensor) in some immersion lithographic apparatuses may have any shape, for example circular, in plan view (i.e. the views of FIG. **6** and FIG. **8**). In this case, the sealing member **600** may have a corresponding circular shape, in plan view.

Examples of surfaces around which a sealing member **600** could be used include: between the body of a table WT, MRT (or cover plate of the table WT, MRT if present) and one or more sensors; between the periphery of the substrate support and a substrate table WT; around the radially outward under-surface of the final element of the projection system; and/or to cover an opening in the top surface of the substrate table WT, for example between an engagement portion of a removable bridge which may serve as a shutter member during substrate swap, and the top surface of a table MRT, WT. Alternatively or additionally, a sealing member **600** may be used to provide a surface with a specific physical property, for example a contact angle with respect to the immersion liquid, such as lyophobic (for example hydrophobic) surface. The sealing member **600** in this context may serve as a surface member, altering the surface which the sealing member covers.

A conventional sealing member (which may be referred to as a "sticker") is made of a metal, such as stainless steel. Such a stainless steel sealing member is very stiff. Typically, it may have a Young's modulus of about 200 GPa. The stainless steel sealing member would typically be attached to the surfaces of the components which are being sealed using an adhesive, such as an adhesive or glue layer. The stiffness of the adhesive is generally much lower than the stiffness of the stainless steel sticker. Furthermore, the adhesive generally has a visco-elastic property, and so may take a significant period of time to return to its original shape after being deformed. This has an impact on the force coupling between the two surfaces that are being sealed, as explained below in relation to FIGS. **9** and **10**.

A conventional sealing member such as that described above is shown in cross section in FIG. **9**. As shown, a conventional sealing member **500** has a conventional upper stainless steel seal portion **520** and a conventional adhesive layer **510**. In the example shown in FIG. **9**, the conventional sealing member **500** is being used to seal a gap **700** having a width x between a TIS sensor **310** and the top surface of a table, such as a substrate table WT (or a cover plate of the table if

present). As noted above, a sealing member **500** of an appropriate shape (in plan view) could be used to seal a gap between any two or more components.

FIG. **10** shows a situation where relative movement between the two components forming the gap being sealed has occurred, i.e. in the frame of reference of one of the components, there is motion of one of the components relative to the other. In the example shown in FIG. **10**, the TIS sensor **310** has moved relative to the substrate table WT by a distance dx . The relative movement in the example shown in FIG. **10** is in the x-y plane, i.e. in the plane parallel to the upper surface of the substrate table WT. The movement dx is in a plane parallel to the plane shown in the plan view of FIG. **6**. This relative movement may result from, for example, the relative movement of the substrate table and the projection system during exposure exerting a force on the substrate table WT and/or sensor and/or substrate/substrate support. To achieve the desired speed of relative motion between the substrate table and the projection system for example during scanning or stepping, a large acceleration in the x-y plane is applied to the substrate table, and therefore to an object supported by the substrate table such as the TIS sensor **310**. The acceleration is also applied to the sealing member **500** sealing the gap between the substrate table WT and the sensor. As the object is at least partly attached to the table by the sealing member, the forces generated by the acceleration between the object and the table are at least partly transmitted through the sealing member **500**. The forces may generate a deformation movement dx in the sealing member **500**. The movement dx is undesirable as it represents movement of the object relative to the supporting table, such as the substrate table WT. As the positioning system measures the substrate table, for example, relative to a frame of reference, such as the projection system, the movement dx may introduce an error into the positioning of the object, for example a substrate support **80** relative to the projection system. This may affect accurate positioning and exposure of, for example, a substrate supported by the substrate support **80**.

As can be seen in FIG. **10**, because the conventional sealing portion **520** is made of stainless steel it is relatively stiff. The conventional sealing portion **520** thus experiences very little or no deformation. Thus the shape of the conventional sealing portion **520** remains substantially unchanged between the original position of FIG. **9** and the position shown in FIG. **10** after relative movement of the two components forming the gap **700** being sealed. However, as explained herein, the conventional adhesive layer **510** is much less stiff than the conventional sealing portion **520**. As such, any relative motion between the two components (for example sideways movement of the TIS sensor **310** in the x-y plane relative to the mirror substrate table WT in the example shown in FIG. **9**) is transferred to the conventional adhesive layer **510**. The conventional adhesive layer **510** in the conventional sealing member **500** may thus experience significant deformation. The conventional adhesive layer **510** in the conventional sealing member **500** has a visco-elastic property. So after removal of the force that caused the relative movement between the two components forming the gap being sealed (for example the top surface of the substrate table WT and the TIS sensor **310** in FIG. **10**), there is a delay in the two components WT, **310** returning to their original positions, for example as shown FIG. **9**. The delay results from the time taken for the conventional adhesive layer **510** to return to its original shape and/or position; for example the time for the conventional sealing member to return to its original form as shown in FIG. **9** from the deformed shape of FIG. **10**. The conventional adhesive layer **510** may act as a damper, providing a time-

related force-coupling between the two components WT, 310 to which the sealing member 500 is attached.

In the conventional sealing member 500 shown in FIGS. 9 and 10, because the conventional sealing portion 520 is relatively much stiffer than the conventional adhesive layer 510, almost all of the relative movement between the two components WT, 310 is transferred to the adhesive layer 510. A larger deformation of the conventional adhesive layer results than if the deformation was distributed between the conventional sealing portion 520 and the conventional adhesive layer 510. The conventional adhesive layer 510 may be significantly deformed. After removal of the force which causes relative movement, the sealing member 500, i.e. having the conventional adhesive layer, takes a significant period of time for the conventional adhesive layer 510 to return to its original shape. This behavior is due to the visco-elastic relaxation of the adhesive layer 510. This visco-elastic relaxation can cause a loss of accuracy, because the time-related force-coupling between the two components being sealed causes uncertainty in the relative position between the two components. It may be difficult to determine and/or control the position of one or both of the components to which the conventional sealing member 500 is attached.

The undesirable force coupling effect of a conventional sealing member 500 may cause inaccurate exposure of a substrate W. One or more overlay errors may occur. Characteristic patterns in overlay errors that are attributable to the conventional sealing member 500 may be seen in specific step- and scan-directions. An embodiment of the invention provides a sealing member, for example a construction of sealing member 600, that addresses one or more of the force-coupling problems, for example the time-related force-coupling problem, set out herein.

FIG. 11 shows a sealing member 600 according to an embodiment of the invention. The sealing member 600 has a similar basic configuration to the conventional sealing member 500 in that it has an adhesive layer 610 and a sealing portion 620. However, in an embodiment, the materials used for the adhesive layer 610 and the sealing portion 620 are selected to have one or more specific properties. These one or more properties may help to reduce, or desirably eliminate, the time-related force-coupling problem explained herein in relation to FIGS. 9 and 10.

In an embodiment, the stiffness of the sealing portion 620 is chosen to be significantly lower than that of the conventional sealing portion 520 of the conventional sealing member 500. This can be achieved, for example, by using a thinner (in cross-section) sealing portion 620. In the embodiment shown in FIG. 11, the stiffness of the sealing portion 620 is reduced compared to that of the conventional stainless steel sealing portion 520 by having a lower Young's modulus than the conventional sealing portion 520. The Young's modulus of the conventional sealing portion 520 is typically around 200 GPa. In an embodiment, the Young's modulus of the sealing portion 620 is below or equal to 50 GPa. In an embodiment, the Young's modulus of the sealing portion 620 is reduced to below or equal to 40 GPa. In an embodiment, the Young's modulus of the sealing portion 620 is reduced to below or equal to 30 GPa. In an embodiment, the Young's modulus of the sealing portion 620 is reduced to below or equal to 20 GPa. In an embodiment, the Young's modulus of the sealing portion 620 is reduced to below or equal to 10 GPa. In an embodiment, the Young's modulus of the sealing portion 620 is reduced to below or equal to 5 GPa. In an embodiment, the Young's modulus of the sealing portion 620 is reduced to around 2.5 GPa or below.

To achieve the reduction in Young's modulus in the sealing portion 620 in comparison with the conventional sealing portion 520 (which may be made of stainless steel) the sealing portion 620 is made from a plastic material or polymer. For example, the sealing portion 620 could comprise or consist of one or more of: polyimide, PET, PTFE, polyetheretherketone, or polyaryletheretherketone. The sealing portion 620 may comprise or consist of a polysiloxane, such as dimethylsiloxane, and/or poly(dimethylsiloxane). One or more silicone based polymers may be used. Desirably, any plastic material or polymer used in the sealing portion 620 should have a property of low rate of deterioration under the influence of contact with immersion liquid, for example purified water, and/or of exposure to exposure radiation. Deterioration may be by degradation, disintegration and/or leaching. A material with a low or non-existent leaching rate, for example leaching, may avoid adverse effects resulting from the material contaminating the immersion liquid, which may be, for example, ultrapure water. By way of example only, the leaching number may be less than $3.3 \times 10^{-4} \mu/(\text{cm}^2\text{s})$. The plastic material may be a synthetic or semisynthetic organic amorphous solid material or a material that undergoes a non-reversible change of shape in response to an applied force.

By using a sealing portion 620 with a reduced Young's modulus, a greater portion of any motion of one component relative to the other component forming the gap 700 being sealed is taken up, or accounted for, by deformation of the sealing portion 620. This effect can be seen in FIG. 12. In FIG. 12, there has been relative movement between the components WT, 310 sealed by the sealing member 600 by a distance dx in the x-y plane. The distance dx may be observed by comparing FIG. 11 with FIG. 12. In an embodiment, the distance dx is the same as the relative movement dx for the conventional sealing member 500 in FIG. 10. In an embodiment the Young's modulus of the sealing portion 620 in the sealing member 600 is selected to be similar to the Young's modulus of the adhesive layer 610, as shown in FIG. 12. Therefore, the sealing portion 620 may experience significant deformation in response to the movement dx. (In contrast, in the conventional arrangement shown in FIG. 10, the stiffness of the conventional sealing portion 520 is relatively much larger than that of the adhesive layer 510, and so the conventional sealing portion 520 thus experiences relatively little deformation).

As a result of the significant deformation of the sealing portion 620 of the sealing member 600, when a certain force is applied to the sealing member 600 and a conventional sealing member 500, the force, or stress, acting through the adhesive layer 610 is less than the force, or stress, acting through the conventional adhesive layer 510. The lower force, or stress, acting through the adhesive layer 610 means that, for example, for a certain acceleration of the substrate table WT to which the sealing member 600 and the conventional sealing member 500 are attached, the deformation of the adhesive layer 610 may be less than the deformation of the conventional adhesive layer 510. The time taken for the adhesive layer 610 as compared to the conventional adhesive layer 510 to return to its original shape shown in FIG. 11 after reduction, if not removal, of the force (for example that caused the relative movement between the two components WT, 310 by the distance dx) may be reduced. The deformed sealing portion 620 experiences much less (or substantially no) visco-elastic effect than the adhesive layer 610. This property of the sealing portion 620 may assist in returning the sealing member 600 to its original shape shown in FIG. 11. The sealing portion 620 may assist because the sealing portion 620 will try to return to its original shape more quickly

than the adhesive layer **610**, for example immediately. As a result, the time-related force-coupling between the two components **310**, WT sealed by the sealing member **600** is reduced as compared to a conventional sealing member **500**. The time over which the force transmission between the two components WT, **310** sealed by the sealing member **600** occurs (i.e. the settling time of the adhesive layer **610**) is reduced. Thus, use of the sealing member **600** may help to reduce the occurrence of overlay errors during exposure and the magnitude of the errors.

FIG. **13** shows an arrangement of a conventional sealing member **500'**. This conventional sealing member is the same as that shown in FIGS. **9** and **10**, except in that the adhesive layer **510** is present in discrete portions **510a** and **510b**. The discrete portions **510a**, **510b** are located towards the ends of the width of the conventional sealing member **500**; that is the areas of overlap of the conventional sealing member **500** and the surfaces of the two components which form the gap being sealed. The discrete portions **510a**, **510b** may attach the conventional sealing member **500'** to the two different components forming the gap to be sealed. The arrangement suffers from the undesirable time-related force-coupling effect discussed herein. The force coupling effect may occur because of the visco-elastic deformation of at least one of the discrete adhesive portions **510b**, **510a**.

FIG. **14** shows the deformation of the conventional sealing member **500'** of FIG. **13** in response to a relative movement dx in the x-y plane between the two components WT, **310** to which the conventional sealing member is secured. Because the conventional sealing portion **520'** of the conventional sealing member **500'** is stiffer, for example much stiffer, than the conventional adhesive portions **510a**, **510b**, it remains relatively undeformed in response to the movement dx. Thus, the conventional adhesive portions **510a**, **510b** deform significantly in response to the movement dx. Thus, in an analogous way to the conventional sealing member **500** shown in FIGS. **9** and **10**, on removal of the force that causes in the relative movement dx, a time-related force-coupling effect is generated by the deformation of the conventional adhesive portions **510a**, **510b**. A delay in the components **310**, WT that form the sealed gap **700** returning to their original positions, as shown in FIG. **13**, is caused. The delay in achieving the original position is a result of the visco-elastic relaxation rate of the conventional adhesive portions **510a**, **510b**. The time-related force-coupling, and the associated delay, may lead to overlay errors during exposure.

FIG. **15** shows a sealing member **600'** according to an embodiment of the invention. The sealing member **600'** has the same configuration as the conventional sealing member **500'** shown in FIG. **13**: the sealing member **600'** comprises a sealing portion **620'** and adhesive portions **610a**, **610b**. The adhesive portions **610a**, **610b** are each arranged to attach, or adhere, the sealing portion **620'** to the surface of one of the two components WT, **310** which form the gap **700**, respectively. The adhesive portions **610a**, **610b** may be arranged between the whole of the overlapping area between a surface **310**, WT forming a gap **700** to be sealed and the sealing portion **620'**. Alternatively, the adhesive portions **610a**, **610b** may be arranged between only a part of the overlapping area between a surface **310**, WT forming a gap **700** to be sealed and the sealing portion **620'**. In FIG. **15**, an arrangement in which the adhesive portions **610a**, **610b** are arranged between only a part of the overlapping area between a surface **310**, WT forming a gap **700** to be sealed and the sealing portion **620'** is shown by the shaded area bounded in part by the dashed lines **611a**, **611b**. An arrangement in which the adhesive portions **610a**, **610b** are arranged between only a part of the overlap-

ping area may result in a reduction in the time-related force-coupling of the adhesive portions **610a**, **610b** compared with the arrangement in which the adhesive portions **610a**, **610b** are arranged between the whole of the overlapping area. The adhesive portions **610a**, **610b** may be liquid impermeable in at least some embodiments.

The sealing member **600'** shown in FIG. **15** uses materials for the adhesive portions **610a**, **610b** and the sealing portion **620'** that are chosen to have one or more specific properties. The one or more properties reduce, or desirably eliminate, the time-related force-coupling problem explained herein in relation to the conventional sealing member **500'** shown in FIG. **13**.

The stiffness of the sealing portion **620'** of the embodiment shown in FIG. **15** may be chosen to be significantly lower than that of the conventional sealing portion **520'**, which may be made of stainless steel. The lower stiffness may be achieved by reducing the thickness of the sealing portion **620'**. Additionally or alternatively, as with the sealing member **600** shown in FIG. **11**, the stiffness may be reduced below that of the conventional sealing portion **520'** by reducing the Young's modulus. The comments made herein in relation to the value of the Young's modulus of the sealing portion **620** of the sealing member described with reference to FIG. **11** may be applicable to the value of the Young's modulus of the sealing portion **620'** shown in the embodiment of FIG. **15**. The sealing portion **620'** of FIG. **15** could be made from a similar material to that of the sealing portion **620** of the sealing member **600** described in relation to FIG. **12**. So the sealing portion **620'** may comprise or consist of one or more of: polyimide, PET, PTFE, polyetheretherketone, or polyaryletheretherketone. The sealing portion **620** may comprise or consist of a polysiloxane, such as dimethylsiloxane, and/or poly(dimethylsiloxane). Additionally or alternatively the sealing portion **620'** may comprise or consist of one or more silicone based polymers.

The deformation of the sealing member **600'** according to the embodiment shown in FIG. **15** in response to a relative movement dx between the components **310**, WT which form the gap **700** and to which the sealing member **600'** may be attached, is shown in FIG. **16**. FIG. **16** shows that, in contrast to the conventional arrangement of FIG. **14**, the sealing portion **620'** experiences a deformation, for example a significant deformation, in response to the movement dx. The sealing portion **620'** has a stiffness (for example Young's modulus) that is similar (or more similar than conventionally) to the adhesive portions **610a**, **610b**. As shown in FIG. **16**, the lower stiffness of the sealing portion **620'** results in a significant reduction in the deformation of the adhesive portions **610a**, **610b** as compared with the deformations of the conventional adhesive portions **510a**, **510b** of a conventional sealing member **500'**, as shown in FIG. **14**. As a result the time taken for the components **310**, WT to which the sealing member **600'** is attached to return to their original position (after removal of the force causing the movement dx) as compared to the use of a conventional sealing member **500'** is less. The use of the sealing member **600'** (of FIG. **15**) has a smaller time-related force-coupling effect than the sealing member **500'**. As the time related force coupling effect of the sealing member **600'** and the conventional sealing member **500'** is determined by the respective adhesive portions **510a**, **510b**, **610a**, **610b**, the visco-elastic relaxation time of the adhesive portions **610a**, **610b** is less than for the conventional adhesive portions **510a**, **510b**. Thus the time over which a force-coupling exists between the components **310**, WT forming the sealed gap **700** is reduced. As such, as with the sealing member **600** as

described herein with respect to FIGS. 10 and 11, the number of overlay errors may be reduced and the size of each overlay error may be reduced.

Improvements achieved by an embodiment of the invention in the time-related force-coupling between the two components forming the sealed gap 700 may be by having a sealing member in which the adhesive is provided at discrete portions 610a, 610b as well as a complete layer 610. Embodiments described herein concerns arrangements in which the adhesive is present in the form of part, if not a whole, layer. As such, any feature described herein may be provided to arrangements with an adhesive layer 610, or arrangements with discrete adhesive portions 610a, 610b.

Additionally or alternatively, there may be relative movement between the two components 310, WT forming the gap 700 sealed by the sealing member in a direction perpendicular to the x-y plane, e.g. in the plane of the top surface of the substrate table, and/or parallel to the optical axis of the projection system. The direction may be known as the z direction. The benefits discussed herein in relation to the sealing members 600, 600' described in relation to FIGS. 11, 12, 15 and 16 may apply to relative movement in the z direction between the two components 310, WT forming a gap sealed by the sealing member 600, 600'. The response of the sealing members 500, 600, 500', 600' to such relative movement in the z-direction is shown in FIGS. 17 to 20.

It will be appreciated that forces and/or relative movement between the components WT, 310 sealed by the sealing member 600/600' may be lower, for example significantly lower, in the z-direction than in the x-y plane. As such, the response of the sealing member 600/600' to deformation and/or forces in the z-direction may be less important than the response of the sealing member 600/600' to deformation and/or forces in the x-y plane.

FIG. 17 illustrates the deformation of the conventional sealing member 500 with a conventional adhesive layer 510 and a conventional sealing portion 520. The undeformed shape of this conventional sealing member 500 is shown in FIG. 9. As shown in FIG. 17, relative movement dz in the z direction between the two components 310, WT forming the sealed gap results in little or no deformation of the sealing portion 520. A large deformation occurs in the conventional adhesive layer 510. The noted deformations of the conventional adhesive layer 510 and the conventional sealing member 520 is because the conventional sealing portion 520 has much greater stiffness than the conventional adhesive layer 510. Because of the large deformation of the conventional adhesive layer 510, the time-based force-coupling between the two sealed components 310, WT occurs because of the visco-elastic property of the conventional adhesive layer 510. As a result there may be one or more difficulties in determining and/or controlling the position of one or both of the sealed components being sealed. Consequently a positioning error of the substrate during exposure may occur. Such an error may, for example, relate to focusing error.

The response of a conventional sealing member 500' having adhesive provided at discrete portions 510a, 510b, such as shown in FIG. 13, to relative movement in the z direction of the two components 310, WT sealed by a conventional sealing member 500' is shown in FIG. 19. Because the conventional sealing portion 520' is relatively much stiffer than the conventional adhesive portions 510a, 510b, one or more of the adhesive portions 510a, 510b may experience a relatively large deformation in response to the movement dz. Such movement dz may lead to a similar time-related force-coupling problem as described herein in relation to FIG. 17.

FIG. 18 illustrates the response of a sealing member 600 which may be shown in its undeformed state, in FIG. 11. FIG. 18 shows the sealing member 600 deformed in response to relative movement in the z direction of the two components 310, WT sealed by the sealing member 600. As shown in FIG. 18, because the stiffness of the sealing portion 620 and the adhesive layer 610 is similar, the movement dz is absorbed, or accounted for, in both layers 610, 620. The deformation of the visco-elastic adhesive layer 610 is reduced in comparison with the visco-elastic conventional adhesive layer 510 shown in FIG. 17. The time-related force-coupling problem associated with the visco-elastic relaxation of the adhesive material is reduced in the adhesive layer 610 as compared to the conventional adhesive layer 510. This, in turn, improves the time-based positioning accuracy of the components 310, WT forming the sealed gap 700.

FIG. 20 shows the deformation of the sealing member 600' in response to relative movement in the z direction between the two components 310, WT which form the gap 700. The sealing member 600' is shown in its undeformed state shown in FIG. 15. As shown in FIG. 20, the sealing portion 620' experiences greater deformation than the stiffer conventional sealing portion 520' in response to the relative movement dz. The response of the sealing portion 620' may be because the stiffness of the sealing portion 620' is more similar to the stiffness of adhesive portions 610a, 610b than the stiffness of the conventional sealing portion 520' is to the conventional adhesive portions 510a, 510b. Consequently under application of the same force in the z direction to the sealing member 600' and the conventional sealing member 500', there is less deformation of the adhesive portions 610a, 610b in comparison to the conventional sealing portions 510a, 510b. The time-based force-coupling between the two components 310, WT sealed by the sealing member 600' is less than if the two components were sealed by the conventional sealing member 500'.

In an embodiment, the stiffness of the sealing portion 620 may be chosen to be in the range of from 2% to 200% of (i.e. a factor of 0.02 to 2 times) the stiffness of the adhesive 610. In an embodiment, the stiffness of the sealing portion 620 may be chosen to be in the range of from 5% to 100% of (i.e. a factor of 0.05 to 1 times) the stiffness of the adhesive 610. In an embodiment, the stiffness of the sealing portion 620 may be chosen to be in the range of from 10% to 50% of (i.e. a factor of 0.1 to 0.5 times) the stiffness of the adhesive 610.

The Young's modulus of the sealing portion 620 may be chosen to be no more than 5×10^5 times (i.e. $5 \times 10^7\%$ of) the Young's modulus of the adhesive 610. In an embodiment, the Young's modulus of the sealing portion 620 may be chosen to be in the range of from 1×10^3 to 1×10^5 times (i.e. $1 \times 10^5\%$ to $1 \times 10^7\%$ of) the Young's modulus of the adhesive 610. In an embodiment, the Young's modulus of the sealing portion 620 may be chosen to be in the range of from 2×10^3 to 5×10^4 times (i.e. $2 \times 10^5\%$ to $5 \times 10^6\%$ of) the Young's modulus of the adhesive 610. In an embodiment, the Young's modulus of the sealing portion 620 may be chosen to be around 1×10^4 (i.e. $1 \times 10^6\%$ of) the Young's modulus of the adhesive 610. This can be achieved by, for example, having the sealing portion 620 comprising or consisting of a suitable plastic material or polymer, such as polyimide, PET, PTFE, polyetheretherketone, and/or polyaryletheretherketone. The sealing portion 620 may comprise a polysiloxane, such as dimethylsiloxane, and/or poly(dimethylsiloxane). Additionally or alternatively, the sealing portion 620 may comprise or consist of at least one silicone based polymer.

In an embodiment, the time-related force-coupling effect resulting from the visco-elasticity of the adhesive layer 610

may additionally or alternatively be improved. For example, the time over which the force-coupling occurs due to visco-elastic settling may be reduced. The improvement may be achieved by reducing the damping, for example the damping constant or viscous damping coefficient, of the adhesive **610**. In an embodiment, the viscous damping coefficient of the adhesive is less than or equal to 5×10^6 Ns/m. In an embodiment, the viscous damping coefficient of the adhesive is less than or equal to 2×10^6 Ns/m. In an embodiment, the viscous damping coefficient of the adhesive is less than or equal to 1×10^6 Ns/m. In an embodiment, the viscous damping coefficient of the adhesive is less than or equal to 5×10^5 Ns/m. In an embodiment, the viscous damping coefficient of the adhesive is less than or equal to 2×10^5 Ns/m. In an embodiment, the viscous damping coefficient of the adhesive is less than or equal to 1×10^5 Ns/m. The viscous damping coefficient may be lower than the viscous damping coefficient of the adhesive **510** used in a conventional sealing member **500**. The adhesive **610** may comprise an acrylic adhesive. An acrylic adhesive may comprise an acrylic polymer. The acrylic polymer may have UV cross-linkings. The acrylic polymer may have an acryl group (which may have the structure $[R-C(=O)-CH=CH-R]$). Alternatively or additionally, the adhesive **610** may comprise a silicone adhesive. The silicone adhesive may comprise a compounded solution of polydimethyl siloxane gum and/or resin. The solution may be diluted in toluene.

By using an adhesive with a lower viscous damping coefficient than is conventional, the settling time of the adhesive (for example the adhesive layer **610** or the adhesive portions **610a**, **610b**) is reduced. The force coupling (or force transfer) between the two components forming the gap being sealed may occur over a reduced time period. The time reduction may help to reduce the time-based force-coupling between the two components **310**, **WT** forming the sealed gap. A reduction in the time-based force-coupling between the components **310**, **WT** forming the gap **700** may help to reduce the errors (for example overlay errors) resulting from the time-based force-coupling.

FIG. **26** shows predicted results produced using various values of stiffness (K) of sealing portion **620**, and various different viscous damping coefficients of the adhesive layer **610** of a sealing member **600**. The predicted results are based on a computer simulation. The graph shows the impact of these parameters on the settling time of the adhesive. For the purposes of FIG. **26** at least, the settling time is defined to the time taken for a gap **700** that is sealed to return to within a certain percentage, or distance, of its original size after a displacing force is removed. For example, the settling time may be defined as the time taken for the width of the gap to return to within 0.1 nm of its original width.

As shown by the dashed line ($K=1.82 \times 10^7$ GPa) in FIG. **26**, if the stiffness (K) of the sealing portion **620** is reduced below conventional levels (for example in the manner described herein), the settling time of the adhesive is greatly reduced for all viscous damping coefficients. However, the solid and dot-chain lines (representing $K=1.82 \times 10^8$ GPa and $K=1.82 \times 10^9$ GPa respectively) show that for higher sealing portion **620** stiffness, the settling time can be increased to between 2 and 3 minutes depending on the viscous damping coefficient of the adhesive layer **610**. Thus, FIG. **26** clearly illustrates that both stiffness (K) of sealing portion **620** and viscous damping coefficient of the adhesive layer **610** have a significant impact on the settling time of the adhesive. However, it will be appreciated that values (for all parameters) other than those shown in FIG. **26** may be used.

In an embodiment the time-related force-coupling effect resulting from the visco-elasticity of the adhesive layer **610**

may additionally or alternatively be improved. For example the time over which the force-coupling occurs due to visco-elastic settling may be reduced. The improvement may be achieved by providing adhesive **610** (for example as an adhesive layer **610**) with a Young's modulus of greater than 1 MPa, desirably greater than or equal to 2 MPa. For example, the Young's modulus of the adhesive **610** may be in the range of from 1 MPa to 500 MPa. For example, the Young's modulus of the adhesive **610** may be in the range of from 2 MPa to 200 MPa. For example, the Young's modulus of the adhesive **610** may be in the range of from 5 MPa to 100 MPa. For example, the Young's modulus of the adhesive **610** may be in the range of from 10 MPa to 50 MPa. By providing an adhesive with a suitable Young's modulus (for example in a range above), the amount of deformation of adhesive **610** in response to a given relative movement between the two components being sealed may be reduced. For example, the relative motion may be reduced because a greater proportion of the relative movement is experienced, or absorbed, by the plastic material or polymer sealing portion **620**. The plastic material or polymer sealing portion **620** may experience visco-elastic relaxation over a shorter period of time than the adhesive **610**. Thus the time-related force-coupling may be reduced.

An adhesive suitable for providing the desired Young's modulus may comprise an acrylic adhesive. An acrylic adhesive may comprise an acrylic polymer. The acrylic polymer may have UV cross-linkings. The acrylic polymer may have an acryl group (which may have the structure $[R-C(=O)-CH=CH-R]$). Alternatively or additionally, the adhesive **610** may comprise a silicone adhesive. The silicone adhesive may comprise a compounded solution of polydimethyl siloxane gum and/or resin. The solution may be diluted in toluene.

It will be understood that any of the sealing members **600**, **600'** described herein may be flexible. The degree of flexibility (which may be expressed as the Young's modulus) is determined by the construction and/or materials used for the sealing member **600**, as described herein. This flexibility affects the force coupling (both in terms of magnitude and duration) between the two components forming the gap **700** being sealed.

The sealing members **600**, **600'** described herein may be replaceable. This means that they may be removed, for example, in a non-limiting list, to enable a particular component to be removed, during maintenance, to be replaced or a combination of these purposes. After removing the sealing member **600**, **600'**, the same sealing member **600**, **600'** may be replaced when the apparatus is rebuilt. Alternatively, the sealing member **600**, **600'** may be discarded and another sealing member **600**, **600'** may be used in its place when the apparatus is rebuilt. The sealing member may be disposable.

As described herein, the sealing member **600**, **600'** is a form of a sheet and may be a removable member which may be used to cover, or to bridge, a gap between surfaces. Additionally or alternatively, the sheet member may be removable. The sheet member may be used to provide or repair a surface property, for example a specific contact angle.

A member, referred to as a surface member, which is structurally similar to a sealing member **600**, **600'** according to an embodiment of the invention, may cover a surface of at least one component of a lithographic tool, for example in an immersion system. The surface member may provide the surface of a component with a specific property, for example surface contact angle with respect to immersion liquid, or UV resistance. In an embodiment the surface being covered has none of the physical properties provided by the surface member. The surface member thus provides the property to the surface to which it is applied. In an embodiment, the surface

may have one or more of the properties provided by the surface member. In an embodiment the surface covered by the surface member already has a surface member providing one or more physical properties. The existing surface may have deteriorated, for example degraded or disintegrated. The surface member to be applied may serve as repair patch. The repair patch may cover the damaged surface or may replace an existing surface member, which is removed before the repair patch is applied. The surface member serving as a repair patch could be used to repair a damaged coating with a specific contact angle, for example on a surface, such as the top surface of a table, e.g. a substrate table away from a substrate holder. The surface provided by the member may be exposed to the immersion liquid, for example water such as ultra-pure water, the exposure radiation, or both. A surface exposed to such an environment, for example on repeated occasions, such as a sensor on the substrate table, may deteriorate after a period of time. It is desirable that deterioration of the member is reduced if not prevented. This may extend the lifetime of the member increasing the duration of use and the intervals at which the member should be removed to be replaced.

In the following description, as an embodiment of the invention may cover at least a part of a surface, the sealing portion 620 is referred to as a covering portion 620, the sealing member 600, 600' is referred to a surface member 600, 600' as it provides a new surface to the surface being covered.

In the embodiment described above in relation to FIGS. 11, 12, 15, 16, 18 and 20, the covering portion 620 of the surface member 600, 600' may be made from a plastic material or polymer. In the immersion lithographic apparatus, the surface member 600, 600' may be exposed to DUV radiation (radiation with the wavelength in the range of from 126 nm to 365 nm, for example 150 nm to 300 nm, for example 157 nm, 180 nm to 200 nm (for example 193 nm) and/or 248 nm).

A typical plastic material or polymer may be transparent to DUV radiation (i.e. may transmit DUV radiation). The DUV radiation may react adversely with the adhesive 610. Delamination of the surface member 600, 600' could result. For example the covering portion 620 may become detached from the adhesive layer 610. The adhesive layer 610 may become detached from the surface to which it is adhered. Thus, in an embodiment, the covering portion 620 is opaque to DUV radiation.

The plastic material or polymer used in the covering portion 620 may react adversely with DUV radiation if it is not adequately protected. For example, the plastic material or polymer may be structurally damaged by exposure to DUV radiation. This may result in increased leaching of the plastic material or polymer. The surface contact angle with respect to the immersion liquid of a plastic material may decrease after reacting with DUV radiation. In an embodiment a lyophobic surface may become more lyophilic, or even lyophilic. It may be undesirable for the surface member 600, 600' to have a lyophilic surface. A surface with a certain lyophilicity relative to another may more readily retain immersion liquid than the other surface. A surface which more readily retains liquid may lead to a greater chance of a droplet remaining on the surface. The droplet can evaporate applying a heat load, applying at least one force to the surface, causing the surface to distort. The liquid in the droplet may contain impurities and/or a particle, which may be left on the surface after the droplet evaporates. A droplet may be in the path of a liquid confinement structure. The droplet may collide with a meniscus between the liquid confinement structure 12 and the surface of the surface member on which the droplet is situated. Such a collision could generate a bubble in the immersion liquid confined in the liquid confinement structure 12. Such a

bubble may later be located in the path of radiation from the projection system to a target portion of a substrate W.

It is therefore additionally or alternatively desirable for the covering portion 620 to be resistant to DUV radiation and/or to prevent the DUV radiation being incident on the plastic material or polymer of the covering portion 620.

According to an embodiment of the invention, the covering portion 620 is constructed as shown in FIG. 21. The covering portion 620 comprises three different layers: a layer 621 of plastic material or polymer, a transmission reduction layer 622 and a contact angle layer 623.

As noted herein, the layer 621 of plastic material or polymer may be, for example, polyimide, PET, PTFE, polyetheretherketone, polyaryletheretherketone, and/or polysiloxane. The layer 621 of plastic material or polymer may have a thickness in the range of from 2 μm to 50 μm , in the range of from 3 μm to 30 μm , in the range of from 5 μm to 20 μm , for example around 10 μm . The layer 621 of plastic material or polymer, in this embodiment, is formed adjacent to, for example attached to or adhered to, the adhesive 610.

The adhesive 610 may be a continuous layer 610 of adhesive, such as that shown in FIG. 11. Alternatively, the adhesive 610 may only be formed on discrete areas of the covering portion 620 so as to enable it to be fixed to the surfaces forming the gap being sealed. Such an arrangement of adhesive 610 is shown in FIG. 15.

In the embodiment of FIG. 21, on a surface, for example a top surface, of the layer 621 of plastic material or polymer is a layer 622. The layer 622 may be on the surface of the layer 621 of plastic material or polymer which is opposite to the surface of the layer 621 to which the adhesive 610 is present. The layer 622 serves to reduce the transmission of DUV radiation incident on the layer 621 of plastic material or polymer, for example in comparison with an embodiment in which the layer 622 it is not present. Therefore, the layer 622 may be referred to as a transmission reduction layer 622. Desirably, the transmission reduction layer 622 helps to reduce, if not eliminate, the transmission of DUV radiation to the layer 621 of plastic material or polymer. In an embodiment, in use, the transmission reduction layer 622 is between the DUV radiation source and both (i) the layer 621 of plastic material or polymer, and (ii) the adhesive 610. In this location the transmission reduction layer 622 helps to protect (i) the layer 621 of plastic material or polymer, (ii) the adhesive 610 or (iii) both the layer 621 and the adhesive 610 from DUV degradation. For example, it may act to reduce the rate, if not the occurrence, of deterioration of the layer 621 of plastic material or polymer, adhesive 610, or both, that may occur due to DUV exposure. The deterioration may be leaching of a material into the immersion liquid, degradation (and even disintegration) as a consequence of interaction with UV radiation, perhaps in combination with an interaction with the immersion liquid, for example ultra pure water, or a combination of these deterioration processes. In some embodiments, the transmission reduction layer 622 may have an optical density of 4 (i.e. a transmission of less than 0.0001).

The transmission reduction layer 622 may be opaque to DUV radiation by being absorptive of DUV radiation. The transmission reduction layer 622 may alternatively or additionally be reflective to DUV radiation, and may optionally have an anti-reflective coating. A transmission reduction layer 622 may be formed by an organic, or an inorganic material. In an embodiment, chromium or titanium is used. The thickness of the transmission reduction layer 622 may typically be in the range of from 1 nm to 200 nm so that it is opaque to DUV radiation. Desirably the thickness of the transmission reduction layer 622 may be in the range of from

3 nm to 100 nm. In an embodiment the thickness of the transmission reduction layer **622** may be in the range of from 10 nm to 50 nm. In an embodiment the transmission reduction layer **622** has a thickness in the range of from 20 nm to 40 nm so that it is opaque to DUV radiation. The transmission reduction layer **622** may be in the range of from 25 nm to 30 nm in thickness. If the transmission reduction layer **622** is metallic, then the layer may be, for example, less than or equal to 200 nm, less than or equal to 50 nm, or less than or equal to 30 nm. It is desirable for the transmission reduction layer **622** to be thin so as maintain the stiffness of the covering portion **620**. In an embodiment, the transmission reduction layer **622** does not significantly increase the stiffness of the covering portion **620**.

In the embodiment of the surface member as shown in FIG. **21**, the transmission reduction layer **622** is substantially untransmissive to DUV radiation. The transmission reduction layer **622** has a contact angle layer **623** on its upper surface. The contact angle layer **623** may form an upper surface of the covering portion **620** (i.e. the surface exposed to the radiation and the surface which may contact immersion liquid). The contact angle layer **623** may have a surface to which immersion liquid has a contact angle relative to certain value, a specific range, or even a specific value. In an embodiment the liquid has a contact angle which is greater than or equal to a certain value. The contact angle layer **623** may have a receding contact angle of greater than or equal to 50 degrees, greater than or equal to 60 degrees, greater than or equal to 70 degrees or greater than or equal to 80 degrees. In an embodiment the contact angle layer **623** has a static angle which is greater than or equal to 90 degrees. Such a surface may be considered lyophobic. This may mean that the surface is relatively lyophobic, for example lyophobic relative to another surface. (The term lyophobic may be considered to have the same meaning as liquidphobic and as used herein includes the term hydrophobic).

In an embodiment, the contact angle layer **623** as shown FIG. **21** may be transmissive, or substantially transmissive, to DUV radiation. The contact angle layer **623** may comprise poly(dimethylsiloxane) for example dimethylsiloxane as described in United States Patent Application Publication No. US 2009-0206304 which is hereby incorporated by reference in its entirety. In an embodiment contact angle layer **623** may be resistant to DUV radiation. The contact angle layer **623** may have a thickness in the range of from 0.5 nm to 2000 nm, in the range of from 2 nm to 1000 nm, in the range of from 10 nm to 500 nm, in the range of from 50 nm to 200 nm, or in the range of from 75 nm to 100 nm.

The contact angle layer **623** helps to ensure that the immersion liquid (for example the water such as ultrapure water) is repelled away from the surface of the surface member **600**, **600'**. The immersion liquid moves away from (i.e. does not remain on) the surface of the surface member **600**, **600'**. The contact angle layer **623** helps to reduce the risk of a disadvantageous outcome that may be caused by a droplet remaining on the surface of the surface member **600**, **600'**. Such an outcome may be staining of the surface of the surface member for example caused by evaporation of liquid on the surface, thermal deformation of the surface member **600**, **600'** due to evaporation of liquid on the surface member **600**, **600'**, and/or inclusion of gas bubbles in the immersion liquid in the space **11**.

An embodiment of the surface member **600**, **600'** is shown in FIG. **22**. The surface member **600**, **600'** may have the same or similar functionality to the surface member **600**, **600'** shown in FIG. **21**. The surface member **600**, **600'** of FIG. **22** has an adhesive layer **610** and a covering portion **620**. The

covering portion **620** has a layer **624** that has low, or substantially no, transmission of DUV radiation (also referred to as a transmission reduction layer **624**) and a contact angle layer **625** of plastic material or polymer.

The transmission reduction layer **624** has low, or substantially no transmission of DUV radiation (hereinafter referred to as being opaque to DUV radiation). The transmission reduction layer **624** is provided so as to be present on the adhesive **610**. In use, the transmission reduction layer **624** is between the adhesive **610** and the DUV radiation source. The transmission reduction layer **624** is in contact with the adhesive **620**. The adhesive **620** may or may not be in the form of a layer. The transmission reduction layer **624** may have the same properties, comprise the same material, or both, as the equivalent transmission reduction layer **622** described herein. The thickness of the transmission reduction layer **624** is in the range of from 0.1 μm to 15 μm , in the range of from 1 μm to 10 μm , in the range of from 2 μm to 4 μm , or desirably around 3 μm .

On a surface, for example the top surface, of the transmission reduction layer **624** there is formed a contact angle layer **625** of plastic material or polymer (which herein is referred to as a contact angle layer **625**). In an embodiment as shown in FIG. **22**, the contact angle layer **625** is a plastic material or polymer as is layer **621** described herein. As well as being plastic material or polymer, the contact angle layer **625**, like the contact angle layer **623** described herein, has a contact angle property with respect to immersion liquid and which is resistant to DUV radiation. Even though the DUV radiation may be incident upon the contact angle layer **625** which is a plastic material or polymer, because it is resistant to such DUV radiation, there is little or no deterioration, for example degradation, disintegration, leaching or a combination of these which is seen in the layer **621** if it were exposed to DUV radiation. The relatively high contact angle, for example the at least relative lyophobicity, of the contact angle layer **625** helps to ensure that immersion liquid (for example water such as ultra pure water) is repelled from the covering portion **620**. As shown in FIG. **22**, in an embodiment the surface, e.g. upper surface, of the surface member **600**, **600'** that contacts the immersion liquid and is exposed to the DUV radiation during use, is formed by the contact angle layer **625**.

A suitable material for the contact angle layer **625** (which may be lyophobic, desirably hydrophobic) of plastic or polymer material may be a polysiloxane. A polysiloxane may be, for example, dimethylsiloxane, or poly(dimethylsiloxane) as described in United States Patent Application Publication No. US 2009-0206304 which is hereby incorporated by reference in its entirety. A typical thickness of the contact angle layer **625** of plastic or polymer material may be in the range of from 0.5 nm to 2000 nm, in the range of from 2 nm to 1200 nm, in the range of from 10 nm to 500 nm, in the range of from 50 nm to 200 nm, or in the range of from 75 nm to 100 nm.

FIG. **23** shows an embodiment of surface member **600**, **600'** according to an embodiment of the invention. In the embodiment the surface member **600**, **600'** has an adhesive **610** and a covering portion **620**. The adhesive **610** may or may not be in the form of a layer. The covering portion **620** comprises a lyophobic plastic material or polymer layer **626**, herein after referred to as a surface layer **626**. The surface layer **626** may be a single layer; the covering portion may have a single constituent layer which is the surface layer **626**. The surface layer **626** may have two major surfaces; the adhesive is present on one of the major surfaces of the surface layer **626** and the other major surface forms a surface of the covering portion **620** (and thus the surface member **600**, **600'**). The surface of the covering portion **620** in use contacts

immersion liquid and is a part of the covering portion through which incidental DUV radiation generally first passes.

In an embodiment the surface layer **626** may be made of a plastic material or polymer. The surface layer **626** may be both resistant to DUV radiation and help to reduce the transmission of DUV radiation. In an embodiment the surface layer **626** is opaque to DUV radiation. By virtue of being resistant to DUV radiation, the surface layer **626** does not degrade as a consequence of exposure to DUV radiation. By virtue of reducing the transmission of DUV radiation, or even being opaque to DUV radiation, the surface layer **626** helps to reduce or even helps to prevent the adhesive **610** being exposed to DUV radiation. By reducing or preventing the exposure of the adhesive **610** to DUV radiation, the adverse effects of exposing the adhesive **610** to DUV radiation may be reduced, even prevented.

In the embodiments described herein, the transmission reduction layer **622**, the transmission reduction layer **624**, and the surface layer **626** that each help to reduce the transmission of DUV radiation therethrough may reflect, absorb or both reflect and absorb the DUV radiation. These layers **622**, **624**, **626** may be opaque to DUV radiation by reflecting and/or absorbing DUV radiation. Optionally, a layer which reduces the transmission of DUV radiation (e.g. the transmission reduction layers **622**, **624**, and surface layer **626**) may comprise an anti-reflective coating. As noted above in relation to the transmission reduction layer **622**, any of the layers **622**, **624**, **626** may act, as appropriate, to help protect one or more other layers, which may comprise (i) plastic material or polymer and/or (ii) adhesive, from DUV degradation. For example, the layer may act to reduce the usual increase in deterioration (e.g. leaching, degradation, or disintegration) of the plastic material or polymer present in a layer that may occur due to DUV exposure. In an embodiment the transmission reduction layers **622**, **624** and the surface layer **626** may have an optical density of 4 (i.e. a transmission of less than 0.0001).

In order to produce a layer that absorbs DUV radiation, DUV radiation absorbing particles may be incorporated into a material forming a layer. The particles may, for example, be TiO and Ta₂O₅. The dimensions of the particles may be nano-scale, for example in the range of from 1 to 100 nm, less than or equal to 50 nm, or less than or equal to 10 nm. In an embodiment, the particles are incorporated into the surface layer **626**. The DUV radiation absorbing particles may absorb the DUV radiation without influencing the contact angle interaction properties of the surface layer **626**.

A suitable base material to which the DUV radiation absorbing particles are present for example in the surface layer **626** may be the same as the material present in the contact angle layer **625**, for example a polysiloxane, such as dimethylsiloxane, or poly(dimethylsiloxane).

An embodiment of the surface member **600**, **600'** is shown in FIG. 27. The surface member **600**, **600'** shown in FIG. 27 may have the same or similar purpose to the surface member **600**, **600'** shown in FIGS. 21, 22 and 23.

The covering portion **620** of the surface member **600**, **600'** shown in FIG. 27 has a layer **628** of plastic material or polymer. The covering portion **620** of the surface member **600**, **600'** shown in FIG. 27 has a transmission reduction layer **629**. The transmission reduction layer **629** is on the layer **628** of plastic material or polymer. The covering portion **620** of the surface member **600**, **600'** shown in FIG. 27 has a further transmission reduction layer **627**. The layer **628** of plastic material or polymer is on the further transmission reduction layer **627**. The covering portion **620** of the surface member **600**, **600'** shown in FIG. 27 has a contact angle layer **630**. The

contact angle layer **630** is on the upper surface of the transmission reduction layer **629**. During manufacture, a layer may be formed on a pre-existing adjacent layer.

Some embodiments may not include all of the layers **627**, **628**, **629**, **630** of the covering portion **620**. For example, an embodiment may omit the contact angle layer **630**.

The construction of at least some of the layers of the surface member **600**, **600'** shown in FIG. 27 may be similar to, or the same as, the construction of equivalent layers of the surface member **600**, **600'** shown in FIG. 21. In particular, each of the embodiment of FIG. 21 and the embodiment of FIG. 27 has an adhesive (for example an adhesive layer) **610** on which a covering portion **620** is formed.

The layer **628** of plastic material or polymer of the embodiment shown in FIG. 27 may be similar to, or the same as, the layer **621** of plastic material or polymer in the embodiment of FIG. 21. At least part, if not all, of the description herein relating to the properties (for example dimensions and/or materials and/or mechanical properties) of the plastic material or polymer layer **621** of the embodiment shown in FIG. 21 may apply to the layer **628** of plastic material or polymer in the embodiment of FIG. 27. By way of example, the layer **628** of plastic material or polymer shown in FIG. 27 may comprise polyetheretherketone and/or polyimide. By way of example, the thickness of the layer **628** of plastic material or polymer in the embodiment shown in FIG. 27 may be on the order of 8 to 10 μm. However, it is emphasized that some, if not all, of the ranges of dimensions, and examples of materials, described above in relation to the layer **621** of plastic material or polymer shown in FIG. 21 may apply to the layer **628** of plastic material or polymer shown in FIG. 27.

The transmission reduction layer **629** shown in the embodiment of FIG. 27 may have properties (for example dimensions and/or materials and/or mechanical properties) that are similar to, or the same as, the transmission reduction layer **622** of the embodiment shown in FIG. 21. At least part, if not all of, the description (in terms of, for example, the dimensions and/or materials and/or properties) of the transmission reduction layer **622** provided herein in relation to the embodiment of FIG. 21 may apply to the transmission reduction layer **629** of the embodiment shown in FIG. 27.

By way of example, the transmission reduction layer **629** of the embodiment shown in FIG. 27 may comprise or consist of chromium and/or titanium. The transmission reduction layer **629** may be a metal layer **629**, which may be referred to as a first metal layer **629**. The metal layer **629** may be a metallization layer formed on the layer **628** of plastic material or polymer. In an embodiment, the transmission reduction layer **629** of the embodiment shown in FIG. 27 may be a chromium layer. In an embodiment the transmission reduction layer **629** shown in the embodiment of FIG. 27 may have a thickness in the range of from 60 nm to 75 nm. In an embodiment, the transmission reduction layer **629** of the embodiment shown in FIG. 27 may be a chromium layer with a thickness on the order of 60 nm. However, a part, if not all, of the description herein relating to the transmission reduction layer **622** of the embodiment shown in FIG. 21 (in terms, for example, of the mechanical properties, dimensions, and materials) may apply to the transmission reduction layer **629** of the embodiment shown in FIG. 27.

The contact angle layer **630** of the embodiment shown in FIG. 27 may be similar to, or the same as, the contact angle layer **623** of the embodiment shown in FIG. 21 (for example dimensions and/or materials and/or mechanical properties). A part, if not all, of the description herein relating to the contact angle layer **623** of the embodiment shown in FIG. 21 may apply to the contact angle layer **630** of the embodiment

shown in FIG. 27. By way of example, the contact angle layer 630 of the embodiment shown in FIG. 27 may comprise poly(dimethylsiloxane) for example dimethylsiloxane. For example, the thickness of the contact angle layer 630 of the embodiment shown in FIG. 27 may be on the order of 200 nm. However, these dimensions and materials are by way of example. Part, or all, of the description relating to the contact angle layer 623 of the embodiment shown in FIG. 21 may apply to the contact angle layer 630 of the embodiment shown in FIG. 27.

The covering portion 620 of the surface member 600, 600' shown in FIG. 27 may have a further transmission reduction layer 627. The further transmission reduction layer 627 is in addition to the transmission reduction layer 629 described above. The further transmission reduction layer 627 may be positioned below the layer 628 of plastic material or polymer. The further transmission reduction layer 627 may be on the opposite surface (for example major surface) of the layer 628 of plastic material or polymer to the transmission reduction layer 629. The layer of plastic material or polymer 628 may be positioned between the two transmission reduction layers 627, 629.

The further transmission reduction layer 627 may have properties (for example dimensions and/or materials and/or mechanical properties) that are similar to, or the same as, the transmission reduction layer 629. At least part, if not all, of the description herein relating to the properties (for example dimensions and/or materials and/or mechanical properties) of the transmission reduction layer 622 of the embodiment shown in FIG. 21 may apply to the further transmission reduction layer 627 of the embodiment shown in FIG. 27, except as described otherwise herein.

In an embodiment, the further transmission reduction layer 627 comprises a metal. In an embodiment, the further transmission reduction layer 627 is a metal layer, for example a metallization layer on the layer 628 of plastic material or polymer. Both the further transmission reduction layer 627 and the transmission reduction layer 629 may be metal layers, for example metallization layers. In that case, the further transmission reduction layer 627 may be referred to as the second metal layer, and the transmission reduction layer 629 may be referred to as the first metal layer.

In an embodiment, the further transmission reduction layer 627 may comprise titanium and/or chromium. In an embodiment, the further transmission reduction layer 627 may be a chromium layer. In an embodiment, the thickness of the further transmission reduction layer 627 may be in the range of from 60 nm to 75 nm. One or more of the properties (for example the dimensions, and/or the materials, and/or the mechanical properties) of the further transmission reduction layer 627 of the embodiment shown in FIG. 27 may be similar to, or the same as, the transmission reduction layer 622 of the embodiment shown in FIG. 21. Thus, all of the dimensions, properties, and materials described herein in relation to the transmission reduction layer 622 of the embodiment shown in FIG. 21 may apply to the further transmission reduction layer 627 of the embodiment shown in FIG. 27.

In the embodiment shown in FIG. 27, the sealing member 600, 600' comprises an adhesive 610 (e.g. as an adhesive layer). The properties (for example the dimensions, and/or the materials, and/or the mechanical properties) of the adhesive 610 are may be the same as the properties of the adhesive 610 described elsewhere in this description for example in relation to the embodiments shown in FIGS. 21, 22 and 23. In an embodiment, the thickness of the adhesive 610 of the embodiment shown in FIG. 27 may have a dimension which is in the order of magnitude of 10 μm , desirably about 10 μm .

The further transmission reduction layer 627 (which may be referred to as a second metal layer or, as explained below, a stabilizing layer) may be positioned in the surface member 600, 600' between the layer 628 of plastic material or polymer and the adhesive 610. The covering portion 620 may be secured (e.g. attached) to the adhesive 610 via the further transmission reduction layer 627. The adhesive 610 may be formed or bonded (and therefore adhered) to the covering portion.

The presence of the further transmission reduction layer 627 between the layer 628 of plastic material or polymer and the adhesive 610 in the surface member 600, 600' may be desirable during manufacture, or construction, of the surface member 600, 600'. During manufacture of the surface member 600, 600', the transmission reduction layer 629 is applied to the layer 628 of plastic material or polymer. This may be achieved, for example, by vapor deposition, for example depositing metal particles on the layer 628 of plastic material or polymer to form the transmission reduction layer 629 (which process may be referred to as metallization).

During application of the transmission reduction layer 629 to the layer 628 of plastic material or polymer, stress (for example torsional forces) may build up in and/or between the layers. For example, there may be thermal stress produced during the application of the transmission reduction layer 629 to the layer 628 of plastic material or polymer.

The layer 628 of plastic material or polymer may have sufficiently low stiffness that the typical thermal stress produced during this process (which may nevertheless only be relatively small thermal stress) can cause deformation (for example twisting and/or bending) of the layer 628 of plastic material or polymer if it is not sufficiently supported. This can lead to deformation (for example twisting and/or bending) of the entire surface member 600, 600'. Such deformation may be, for example, during manufacture. If a single transmission reduction layer 629 is applied to the layer 628 of plastic material or polymer, without sufficient support, the resulting surface member 600, 600' may be difficult to handle. For example, it may be difficult to keep the seal member 600, 600' flat (or substantially flat), as may be required for application to a surface.

The stress between the layers of the surface member 600, 600' may alternatively or additionally lead to deformation (for example twisting and/or bending) of the surface member 600, 600' during use. For example, dynamic forces exerted on the surface member 600, 600' could cause the surface member 600, 600' to deform, or could worsen any deformation already present from the manufacturing process. Such dynamic forces could be due to relative movement of the two surfaces forming the gap that the surface member 600, 600' is sealing.

The presence of the further transmission reduction layer 627 may help to reduce, if not prevent, the stress increase within the surface member 600, 600' for example between adjacent layers. The stress that would otherwise be produced during application of the transmission reduction layer 629 to the layer 628 of plastic material or polymer during use may thus be reduced. Unacceptable deformation of the layer 628 of plastic material or polymer, and therefore of the covering portion 620 and the surface member 600, 600' may be avoided. As such, the further transmission reduction layer 627 may act as a support layer, or stabilizing layer, to the layer 628 of plastic material or polymer.

The further transmission reduction layer 627 may apply a force to the layer 628 of plastic material or polymer during its application to the layer 628. The force applied by the further transmission layer 627 may cause stress to build between the further transmission layer 627 and the layer 628 of plastic

material or polymer. The stress (for example torsional force) induced within the covering portion **620** by the further transmission layer **627** may serve to counteract (or balance) the stress (for example torsional force) applied to the layer **628** of plastic material or polymer by the transmission reduction layer **629**. Thus the further transmission layer **627** may serve to at least reduce to an acceptable level, if not prevent, the force applied by the transmission reduction layer **629** to the layer **628** of plastic material or polymer from causing deformation. The further transmission reduction layer **627** may balance internal torsion force produced by the transmission reduction layer **629** on the layer **628** of plastic material or polymer. The further transmission reduction layer **627** may be referred to as a stabilizing layer **627**, for example a stabilizing metal layer **627**.

The embodiment shown in FIG. **27** may be particularly appropriate in an embodiment in which the transmission reduction layer **629** is a metal layer. Such a metal layer may be formed, for example, by depositing metal ions (such as chromium ions) on the surface of the layer **628** of plastic material or polymer. Such layer may be referred to as a metallization or metalized layer. The layer may be a coating of metal, for example a film, which is deposited on the layer **628** of plastic or polymer material. Metal ion deposition can lead to a build up of stress due to inter-molecular forces. Therefore, in such an embodiment, the application of the further transmission reduction layer **627** to the opposite surface of the layer **628** of plastic material or polymer can act to balance these forces. In an embodiment, the properties (for example the dimensions, and/or materials, and/or mechanical properties) of the further transmission reduction layer **627** may be similar to, or the same as, the properties of the transmission reduction layer **629**. Having a transmission reduction layer **629** and a further transmission reduction layer **627** with similar, if not the same, properties may help to ensure that the forces are balance appropriately. Little, or no, deformation of the covering portion may be produced.

In order to manufacture a surface member **600**, **600'** with both a transmission reduction layer **629** and a further transmission reduction layer **627**, such as that shown in FIG. **27**, each transmission reduction layer may be applied in a plurality of alternating steps. In an embodiment, a fraction (for example of the thickness) of one of the transmission reduction layer **629** and the further transmission reduction layer **627** may be firstly applied to the layer **628** of plastic material or polymer. Next, a fraction of the other one of the transmission reduction layer **629** and the further transmission reduction layer **627** may be applied to the opposite surface (for example major surface) of the layer **628** of plastic material or polymer. This process, of applying a fraction of each of the transmission reduction layers **627**, **629** to opposite surfaces of the layer **628** of plastic material or polymer alternately, may be repeated until both of the transmission reduction layers **627**, **629** have been completely applied. Forming the transmission reduction layers **627**, **629** in steps as described above may ensure that no unacceptable torsional forces and/or distortion occurs during manufacture.

Any suitable fraction of transmission reduction layer may be applied at each step. For example, a fraction of the transmission reduction layer **627**, **629** in the range of from 1% to 50% may be applied at each step. The smaller the percentage of the layer that is applied in each step, greater the number of total steps required to produce each full layer. In an embodiment, the total number of steps required to form each of the transmission reduction layers **627**, **629** may be in the range of from 2 to 100 steps, for example in the range of from 3 to 50

steps, for example in the range of from 4 to 25 steps, for example in the range of from 5 to 20 steps, for example in the range of from 6 to 10 steps.

In an embodiment, the further transmission reduction layer **627**, is configured (for example in terms of dimensions and materials) to reduce the transmission of UV (for example DUV) radiation. It will be appreciated that in another embodiment the further transmission reduction layer **627** does not reduce the transmission of radiation. To act as a stabilizing layer it need not be necessary for the further transmission reduction layer to reduce the transmission of UV radiation. However, it may be desirable for the further transmission reduction layer **627** to further reduce the transmission of radiation (for example UV radiation) that penetrates the covering portion **620** through to the adhesive **610**. The adhesive **610** may be more susceptible to degradation through UV exposure than the layer **628** of plastic material or polymer. The further transmission reduction layer **627** may help to reduce the UV radiation from reaching the adhesive **610**.

The description herein focuses on the use of the surface member **600**, **600'** in an immersion lithographic apparatus. However, it will be appreciated that the surface members **600**, **600'** described herein may be useful in other applications. For example, the surface members **600**, **600'** described herein may be particularly applicable as surface members which are exposed to pure water and/or UV radiation and/or high stresses and strains for example during use. In particular, the surface members **600**, **600'** described herein may be useful as surface members on any surfaces exposed to a UV source, such as solar radiation. One additional application, by way of example only, may thus be a window, such as an external window to which a lateral force may be repetitively applied.

For a surface member **600**, **600'** that is not exposed to DUV radiation, there is no requirement for the surface member **600**, **600'** to be at least DUV radiation resistant or at least opaque to DUV radiation. Thus, for example, the DUV transmission reduction layers **622**, **624** (that are at least partially opaque to DUV radiation) as described herein with reference to FIGS. **21** and **22** may be omitted. In an embodiment as shown in FIG. **23**, there may be no requirement to include the DUV radiation absorbing elements in the surface layer **626**. Such a surface member could be used to cover a surface of a component of a lithographic tool, for an immersion system, for example to seal a gap between surfaces, that are infrequently exposed, desirably not exposed, to DUV radiation. Such a surface may be exposed to stray DUV radiation. The surface may be outside a path of radiation from the projection system to a surface facing the projection system, or may be in the path of radiation during a non-exposing phase of operation.

FIGS. **24** and **25** show non-limiting examples of locations that are infrequently or never exposed to DUV radiation and at which surface members **600**, **600'** in the form of surface members **601**, **602**, **603**, **604** may be provided. In an immersion lithographic apparatus, it is desirable to retain the immersion liquid in place when, for example, changing a substrate. To this end, a surface of a shutter member (such as a bridge, a closing disc, or a measurement table) may replace the surface of the substrate (or substrate table) which is used to retain immersion liquid in space **11** during, e.g., substrate swap. A bridge (for example a swap bridge) may be slid underneath the projection system when a substrate (and in some cases a substrate table supporting the substrate) is removed after exposure. In an embodiment, a closing disc may be used to retain immersion liquid around the final element of the projection system, for example during substrate exchange. In an embodiment, a measurement table may be introduced underneath the projection system in place of a substrate table.

FIG. 24 shows a swap bridge 86 comprising a bridge body 87 and at least one engagement portion 88 for engaging the bridge body 87 to a substrate table WT. The engagement portion 88 may additionally or alternatively be for engaging the bridge body 87 to a closing disc, or a measurement table (which is arranged to be unable to support a substrate for exposure). A surface member 601 may be provided on a surface of the bridge body 87. Such a surface member 601 may be provided to a surface of any table shutter member. The swap bridge 86 may be arranged as shown in FIG. 24 which is an example of a removable bridge between two tables. Additionally or alternatively, a surface member 602 may be provided to cover a gap 702 between a surface of the engagement portion 88 and the substrate table WT.

FIG. 25 shows the region around the last optical element 91 of the projection system PS. A surface member 603 may be provided on a surface of the last optical element 91. A surface on which the surface member 603 may be provided may be between the last optical element 91 and a liquid confinement structure 12. So the surface member 603 may be provided on a surface that faces, in use, the liquid confinement structure 12. A surface member 604 may additionally or alternatively be provided on a surface of the liquid confinement structure 12 that faces the projection system PS, for example the last optical element 91 of the projection system PS.

As explained herein, the surface members 601, 602, 603, 604 shown in FIGS. 24 and 25 are generally infrequently, or never, exposed to DUV radiation. For example, they may be provided at positions which the beam from the projection system PS is not directed and/or doesn't pass through. However, such a surface may be exposed to stray DUV radiation. This means that they need not be resistant to DUV radiation and/or need not be opaque to DUV radiation. Note an exception may be the surface of a measurement table MRT around a sensor held by the table. Exposure radiation may be directed at the measurement table surface surrounding the sensor.

The thickness of a surface member 600, 600' (e.g. in a direction perpendicular to a major surface of the surface member 600, 600'), for example as shown in FIG. 21, 22 or 23, may be in the range of from 1 μm to 30 μm , in the range of from 2 μm to 25 μm , in the range of from 3 μm to 20 μm , in the range of from 4 μm to 15 μm , or in the range of from 5 μm to 10 μm . A surface member 600, 600' having thicknesses in one or more of these ranges above may facilitate handling and/or positioning for example by reference to the lower limit of the respective ranges. By reference to the upper limit of the range, a step height difference with respect to a surface on which the surface member is applied. The effect change in dimensions of the component to which the surface member is applied is limited, desirably minimized, so that the dimension of the component remains in the intended specified manufacturing range. For example, if the dimensions of a surface member applied to the surface of a substrate table are too large, there may be risk of collision with a liquid confinement structure as there is relative movement between the substrate table and the liquid confinement structure. By limiting the thickness of the surface member, collision risk may be reduced. However, it is possible to have a surface member 600, 600' according to an embodiment of the invention with a thickness below 1 μm , or above 30 μm .

In an embodiment, the surface member 600, 600' (which may be a sealing member 600, 600') may be provided in the form of a kit. The kit may comprise: a sealing or covering portion; and an adhesive. The sealing or covering portion may be a plastic material or polymeric sealing or covering portion. The sealing or covering portion may, by way of non-limiting example, take the form of the portion 620 shown in any one of

FIGS. 21 to 23. In such a kit, the adhesive and the sealing or covering portion may be separate. The kit may be used to form a sealing member 600, 600' or surface member 600, 600', such as described herein. The adhesive in the kit may be used to adhere the sealing or covering portion to at least a part of one or more surfaces. The adhesive in the kit may be used to form, for example, an adhesive layer (such as the adhesive layer 610 shown in FIG. 11), or discrete adhesive portions (such as the portions 610a, 610b shown in FIG. 15). The kit may include a surface member 600, 600' (or the components of a surface member 600, 600') precut so they may be applied in a specific location, for example around an object such as a sensor 310, 320 held on a table WT, MRT. The kit may include a surface member 600, 600' provided as a blank for cutting shortly before applying the surface member 600, 600'.

Although specific reference may be made in this text to the use of lithographic apparatus in the manufacture of ICs, it should be understood that the lithographic apparatus described herein may have other applications, such as the manufacture of integrated optical systems, guidance and detection patterns for magnetic domain memories, flat-panel displays, liquid-crystal displays (LCDs), thin-film magnetic heads, etc. The skilled artisan will appreciate that, in the context of such alternative applications, any use of the terms "wafer" or "die" herein may be considered as synonymous with the more general terms "substrate" or "target portion", respectively. The substrate referred to herein may be processed, before or after exposure, in for example a track (a tool that typically applies a layer of resist to a substrate and develops the exposed resist), a metrology tool and/or an inspection tool. Where applicable, the disclosure herein may be applied to such and other substrate processing tools. Further, the substrate may be processed more than once, for example in order to create a multi-layer IC, so that the term substrate used herein may also refer to a substrate that already contains multiple processed layers.

The terms "radiation" and "beam" used herein encompass all types of electromagnetic radiation, including ultraviolet (UV) radiation (e.g. having a wavelength of or about 365, 248, 193, 157 or 126 nm). The term "lens", where the context allows, may refer to any one or combination of various types of optical components, including refractive and reflective optical components.

While specific embodiments of the invention have been described above, it will be appreciated that the invention may be practiced otherwise than as described. For example, the embodiments of the invention may take the form of a computer program containing one or more sequences of machine-readable instructions describing a method as disclosed above, or a data storage medium (e.g. semiconductor memory, magnetic or optical disk) having such a computer program stored therein. Further, the machine readable instruction may be embodied in two or more computer programs. The two or more computer programs may be stored on one or more different memories and/or data storage media.

One or more of the controllers described herein may each or in combination be operable when the one or more computer programs are read by one or more computer processors located within at least one component of the lithographic apparatus. The controllers may each or in combination have any suitable configuration for receiving, processing, and sending signals. One or more processors are configured to communicate with the at least one of the controllers. For example, each controller may include one or more processors for executing the computer programs that include machine-readable instructions for the methods described above. The controllers may include data storage medium for storing such

computer programs, and/or hardware to receive such medium. So the controller(s) may operate according to the machine readable instructions of one or more computer programs.

One or more embodiments of the invention may be applied to any immersion lithography apparatus, in particular, but not exclusively, those types mentioned above and whether the immersion liquid is provided in the form of a bath, only on a localized surface area of the substrate, or is unconfined. In an unconfined arrangement, the immersion liquid may flow over the surface of the substrate and/or substrate table so that substantially the entire uncovered surface of the substrate table and/or substrate is wetted. In such an unconfined immersion system, the liquid supply system may not confine the immersion fluid or it may provide a proportion of immersion liquid confinement, but not substantially complete confinement of the immersion liquid.

A liquid supply system as contemplated herein should be broadly construed. In certain embodiments, it may be a mechanism or combination of structures that provides a liquid to a space between the projection system and the substrate and/or substrate table. It may comprise a combination of one or more structures, one or more fluid openings including one or more liquid openings, one or more gas openings or one or more openings for two phase flow. The openings may each be an inlet into the immersion space (or an outlet from a fluid handling structure) or an outlet out of the immersion space (or an inlet into the fluid handling structure). In an embodiment, a surface of the space may be a portion of the substrate and/or substrate table, or a surface of the space may completely cover a surface of the substrate and/or substrate table, or the space may envelop the substrate and/or substrate table. The liquid supply system may optionally further include one or more elements to control the position, quantity, quality, shape, flow rate or any other features of the liquid.

In an embodiment, there is disclosed a sealing member kit for sealing a gap formed between at least two surfaces of an immersion lithographic apparatus from immersion liquid ingress, the sealing member kit for forming a sealing member, the sealing member kit comprising a plastic material or polymeric sealing portion and an adhesive to attach the sealing portion to a surface of an immersion lithographic apparatus, wherein the stiffness of the plastic material or polymeric sealing portion is no more than 100% of the stiffness of the adhesive.

In an embodiment, the Young's modulus of the plastic material or polymeric sealing portion is no more than or equal to a factor of 5×10^5 times the Young's modulus of the adhesive. In an embodiment, the viscous damping coefficient of the adhesive is less than or equal to 2×10^6 Ns/m. In an embodiment, the Young's modulus of the adhesive is greater than or equal to 2 MPa.

In an embodiment, there is disclosed a sealing member kit for sealing a gap formed between at least two surfaces of an immersion lithographic apparatus from immersion liquid ingress, the sealing member kit comprising a plastic material or polymeric sealing portion, and an adhesive to attach the sealing portion to a surface of an immersion lithographic apparatus, wherein the Young's modulus of the adhesive is greater than or equal to 2 MPa.

In an embodiment, the viscous damping coefficient of the adhesive is less than or equal to 2×10^6 Ns/m.

In an embodiment, there is provided a sealing member kit for sealing a gap formed between two surfaces of an immersion lithographic apparatus from immersion liquid ingress, the sealing member kit comprising a plastic material or polymeric sealing portion, and an adhesive to attaching the sealing

portion to a surface of an immersion lithographic apparatus, wherein the damping constant of the adhesive is less than or equal to 2×10^6 Ns/m.

In an embodiment, the Young's modulus of the adhesive is greater than or equal to 2 MPa. In an embodiment, the stiffness of the plastic material or polymeric sealing portion is no more than 100% of the stiffness of the adhesive layer. In an embodiment, the Young's modulus of the plastic material or polymeric sealing portion is no more than or equal to a factor of 5×10^5 times the Young's modulus of the adhesive layer.

With respect any of the foregoing kits: In an embodiment, the Young's modulus of the plastic material or polymeric sealing portion is less than or equal to 5 GPa. In an embodiment, the plastic material or polymeric sealing portion comprises polyimide, PET, PTFE, polyetheretherketone, polyaryletheretherketone, or polysiloxane. In an embodiment, the adhesive layer comprises a silicon adhesive or an acrylic adhesive. In an embodiment, the plastic material or polymeric sealing portion is opaque to DUV radiation. In an embodiment, the upper surface of the plastic material or polymeric sealing portion is lyophobic. In an embodiment, the plastic material or polymeric sealing portion has a first surface and a second surface, and comprises a layer of plastic material or polymer to which the adhesive adheres and an opaque layer adjacent the layer of plastic material or polymer and between the layer of plastic material or polymer and the first surface of the sealing portion, the opaque layer being opaque to DUV radiation. In an embodiment, the sealing member kit further comprises a lyophobic layer adjacent the opaque layer, the lyophobic layer forming the first surface of the sealing portion. In an embodiment, the plastic material or polymeric sealing portion has a first surface and a second surface, and comprises an opaque layer to which the adhesive adheres, the opaque layer being opaque to DUV radiation, and a lyophobic layer of plastic material or polymer adjacent the opaque layer, the lyophobic layer of plastic material or polymer forming the first surface of the sealing portion. In an embodiment, the plastic material or polymeric sealing portion has a first surface and a second surface, and comprises a lyophobic layer of plastic material or polymer to which the adhesive adheres, the lyophobic layer of plastic material or polymer being opaque to DUV radiation. In an embodiment, the sealing portion is impermeable to liquid. In an embodiment, the sealing member kit is configured to seal the gap between a substrate table of an immersion lithographic apparatus and a sensor positioned on the substrate table. In an embodiment, the sealing member kit is configured to seal the gap formed between a substrate table of an immersion lithographic apparatus and a substrate support of the immersion lithographic apparatus, the substrate support configured to support a substrate. In an embodiment, the plastic material or polymeric sealing portion is in the form of a patch to repair a damaged surface in an immersion lithographic apparatus. In an embodiment, the patch is arranged to be used to repair a damaged surface of a substrate table.

In an embodiment, there is provided a sealing member comprising the sealing portion and adhesive of the sealing member kit. In an embodiment, the adhesive is in the form of a layer. In an embodiment, the sealing member is disposable.

In an embodiment, there is provided an immersion lithographic apparatus comprising the sealing member. In an embodiment, the immersion lithographic apparatus comprises a substrate table constructed to hold a substrate, and a sensor positioned on the substrate table, wherein the sealing member, in use, is positioned between the sensor and the substrate table and adhered at one end to the sensor and at the other end to the substrate table.

In an embodiment, there is provided a method of sealing a gap between a first surface and a second surface of an immersion lithographic apparatus comprising adhering the sealing member to the first surface, and to the second surface, thereby bridging the gap between the first and second surfaces of the immersion lithographic apparatus. In an embodiment, the sealing member covers the gap, at least a part of the first surface and at least a part of the second surface, the sealing member having a first overlapping portion overlapping the at least a part of the first surface and a second overlapping portion overlapping the at least a part of the second surface, wherein the adhering of the sealing member to the first surface and to the second surface comprises adhering the first overlapping portion and the second overlapping portion to at least a part of each of the first surface and the second surfaces respectively.

The descriptions above are intended to be illustrative, not limiting. Thus, it will be apparent to one skilled in the art that modifications may be made to the invention as described without departing from the scope of the claims set out below.

The invention claimed is:

1. A sealing member kit for sealing a gap formed between at least two surfaces of an immersion lithographic apparatus from immersion liquid ingress, the sealing member kit comprising:

a plastic material or polymeric sealing portion sized to cover the gap; and

an adhesive portion to attach the sealing portion to at least one of the surfaces of the immersion lithographic apparatus, the adhesive portion being on only one side of the sealing portion,

wherein the stiffness of the sealing portion is no more than 100% of the stiffness of the adhesive portion.

2. The sealing member kit according to claim 1, wherein the Young's modulus of the material of the sealing portion is no more than or equal to a factor of 5×10^5 times the Young's modulus of the material of the adhesive portion.

3. The sealing member kit according to claim 1, wherein the viscous damping coefficient of the material of the adhesive portion is less than or equal to 2×10^6 Ns/m.

4. The sealing member kit according to claim 1, wherein the Young's modulus of the material of the adhesive portion is greater than or equal to 2 MPa.

5. The sealing member kit according to claim 1, wherein the Young's modulus of the material of the plastic material or polymeric sealing portion is less than or equal to 5 GPa.

6. The sealing member kit according to claim 1, wherein the material of the plastic material or polymeric sealing portion comprises polyimide, PET, PTFE, polyetheretherketone, polyaryletheretherketone, or polysiloxane.

7. The sealing member kit according to claim 1, wherein the material of the adhesive portion layer comprises a silicone adhesive or an acrylic adhesive.

8. The sealing member kit according to claim 1, wherein the plastic material or polymeric sealing portion is opaque to DUV radiation.

9. The sealing member kit according to claim 1, wherein the upper surface of the plastic material or polymeric sealing portion is lyophobic.

10. The sealing member kit according to claim 1, wherein the plastic material or polymeric sealing portion has a first surface and a second surface, and comprises:

a layer of plastic material or polymer to which the adhesive portion adheres; and

an opaque layer adjacent the layer of plastic material or polymer and between the layer of plastic material or

polymer and the first surface of the sealing portion, the opaque layer being opaque to DUV radiation.

11. The sealing member kit according to claim 1, wherein the plastic material or polymeric sealing portion has a first surface and a second surface, and comprises:

an opaque layer to which the adhesive portion adheres, the opaque layer being opaque to DUV radiation; and

a lyophobic layer of plastic material or polymer adjacent the opaque layer, the lyophobic layer of plastic material or polymer forming the first surface of the sealing portion.

12. The sealing member kit according to claim 1, wherein the plastic material or polymeric sealing portion has a first surface and a second surface, and comprises a lyophobic layer of plastic material or polymer to which the adhesive portion adheres, the lyophobic layer of plastic material or polymer being opaque to DUV radiation.

13. The sealing member kit according to claim 1, wherein the sealing portion is impermeable to liquid.

14. The sealing member kit according to claim 1 sealing the gap between a substrate table of an immersion lithographic apparatus and a sensor positioned on the substrate table.

15. The sealing member kit according to claim 1 sealing the gap formed between a substrate table of an immersion lithographic apparatus and a substrate support of the immersion lithographic apparatus, the substrate support configured to support a substrate.

16. A sealing member comprising:

a plastic material or polymeric sealing portion; and

an adhesive portion to attach the sealing portion to a surface of an immersion lithographic apparatus, the adhesive portion being on only one side of the sealing portion, wherein the stiffness of the sealing portion is no more than 100% of the stiffness of the adhesive portion.

17. An immersion lithographic apparatus comprising the sealing member according to claim 16.

18. A method of sealing a gap between a first surface and a second surface of an immersion lithographic apparatus comprising adhering a sealing member to the first surface and to the second surface, thereby bridging the gap between the first and second surfaces of the immersion lithographic apparatus, the sealing member having a plastic material or polymeric sealing portion and an adhesive portion to attach the sealing portion to a surface of an immersion lithographic apparatus, the adhesive portion being on only one side of the sealing portion, wherein the stiffness of the sealing portion is no more than 100% of the stiffness of the adhesive portion.

19. A sealing member sealing a gap formed between two surfaces of an immersion lithographic apparatus from immersion liquid ingress, the sealing member comprising:

a plastic material or polymeric sealing portion covering the gap; and

an adhesive attaching the sealing portion to at least one of the surfaces of the immersion lithographic apparatus, the at least one surface being next to an end of the gap and the adhesive being on only one side of the sealing portion,

wherein the damping constant of the adhesive is less than or equal to 2×10^6 Ns/m.

20. A sealing member kit for sealing a gap formed between at least two surfaces of an immersion lithographic apparatus from immersion liquid ingress, the sealing member comprising:

a plastic material or polymeric sealing portion covering the gap; and

an adhesive attaching the sealing portion to at least one of the surfaces of the immersion lithographic apparatus,

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the at least one surface being next to an end of the gap
and the adhesive being on only one side of the sealing
portion,
wherein the Young's modulus of the adhesive is greater
than or equal to 2 MPa.

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